

Electron microscopy

PH 673

Nanoscience and nanotechnology

November 19, 2025

TEM: the beginning

Ruska & Knoll



Fig. 6. The first electron microscope. The publication (48) contained only one cross-sectional drawing corresponding to Figure 5. This photograph, reproduced here for the first time, with M. Knoll and the author – was actually taken several years later, on 8 February 1944.

Invention and Evolution of the Modern TEM

- In 1932, invented by E. Ruska *et al.*
- In 1986, Ruska received the Nobel Prize



Nobel Prize in Physics 1986



Ernst Ruska (Fritz-Haber-Institut der Max-Planck-Gesellschaft, Germany)

Gerd Binnig (IBM Zurich Research Laboratory, Switzerland)

Heinrich Rohrer (IBM Zurich Research Laboratory, Switzerland)

The Nobel Prize in Physics 1986 was divided, one half awarded to Ernst Ruska *"for his fundamental work in electron optics, and for the design of the first electron microscope"*, the other half jointly to Gerd Binnig and Heinrich Rohrer *"for their design of the scanning tunneling microscope"*.

Transmission Electron Microscope

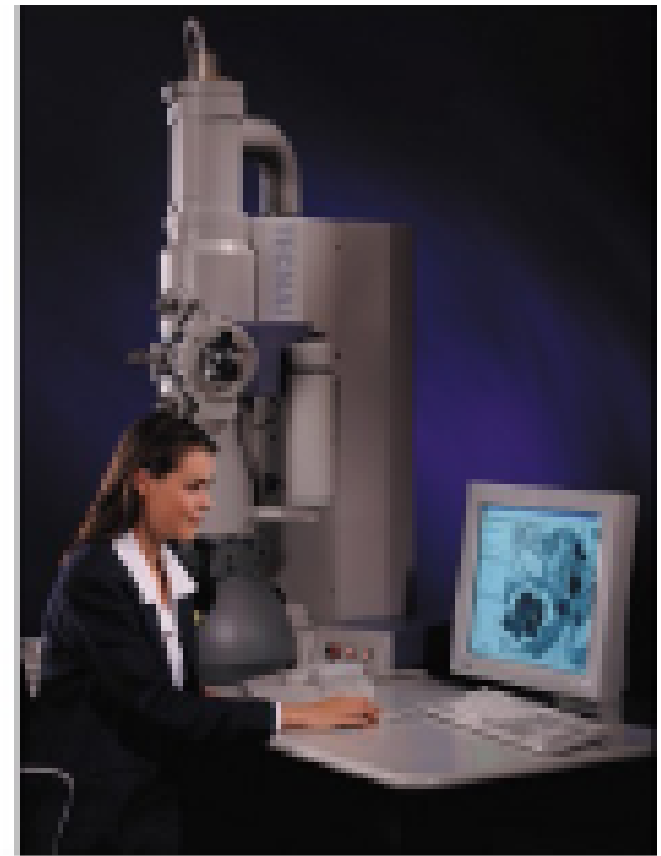
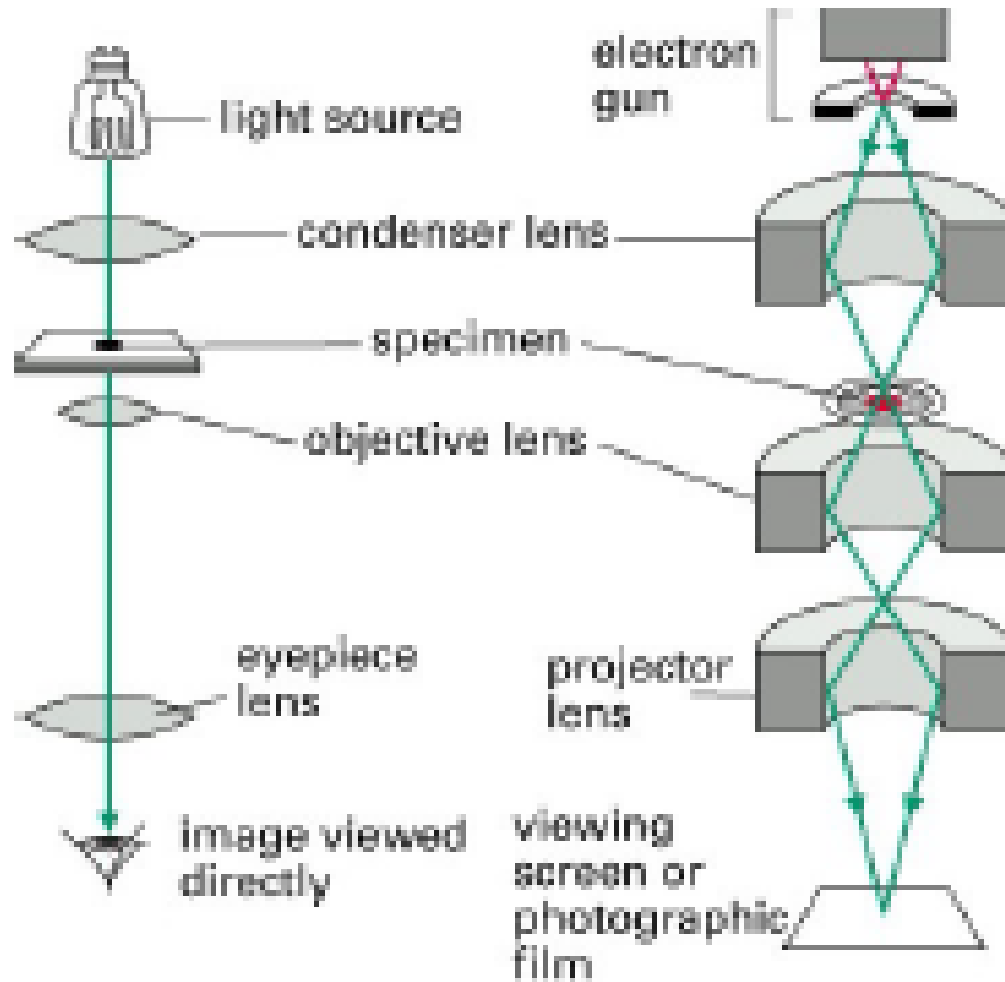
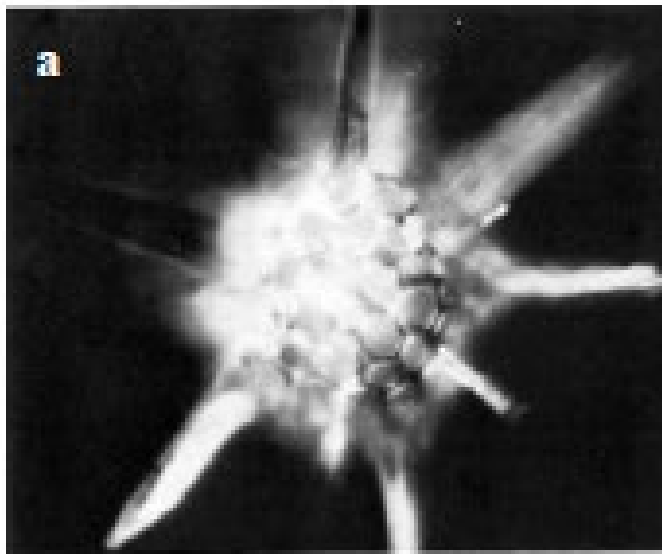


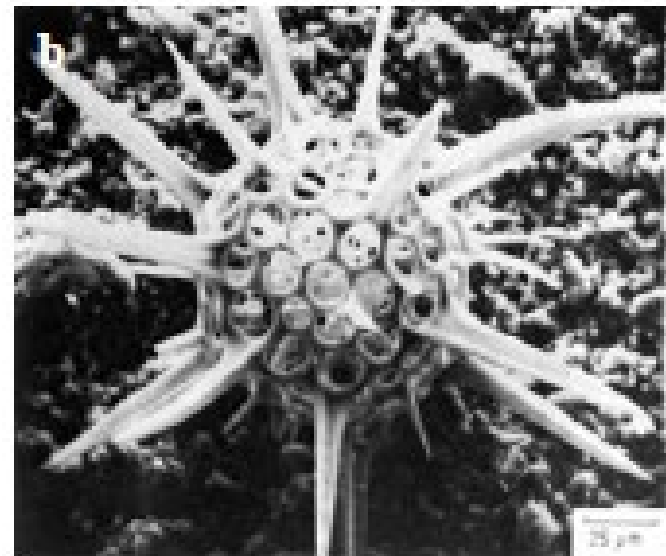
Figure 9-22. Molecular Biology of the Cell, 4th Edition.

Optical vs electron microscopy

Depth of Field or Depth of Focus



OM image



SEM image

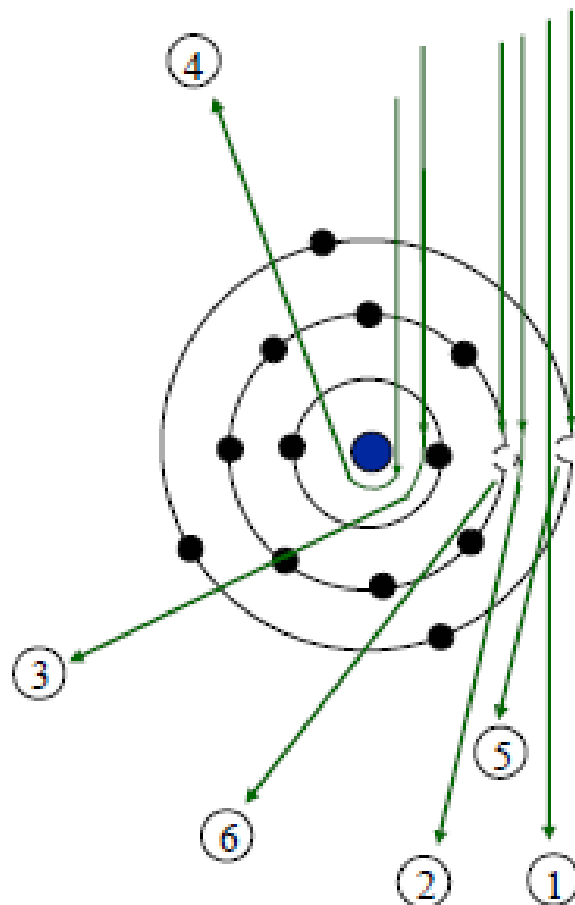
Radiolarian, taken from Goldstein *et al.* (1992)

Basic electron optics

- Electrons and ions are charged particles, they can be accelerated in a \mathbf{E} field.
- The trajectory of an accelerated charged particle can be deflected by \mathbf{E} and/or \mathbf{B} field.
- According to *de Broglie*, the accelerated (high-energy) particles also behave like waves.

Interaction of high energy (\sim kV) electrons with (solid) materials-I

Interaction with an Atom

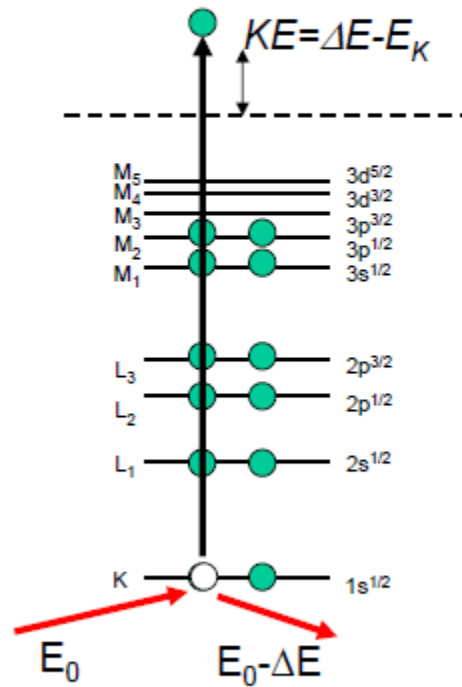


- ① Unscattered
- ② Low angle elastically scattered
- ③ High angle elastically scattered
- ④ Back scattered
- ⑤ Outer shell inelastically scattered
- ⑥ Inner shell inelastically scattered



Electron Shells and Transitions

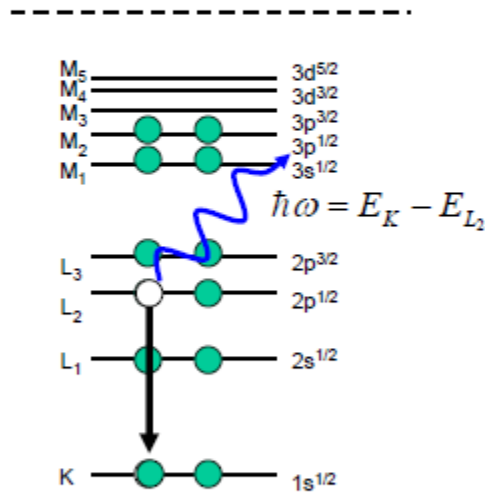
1) Ionization



Measured by EELS

(Electron Energy Loss Spectroscopy
in a TEM)

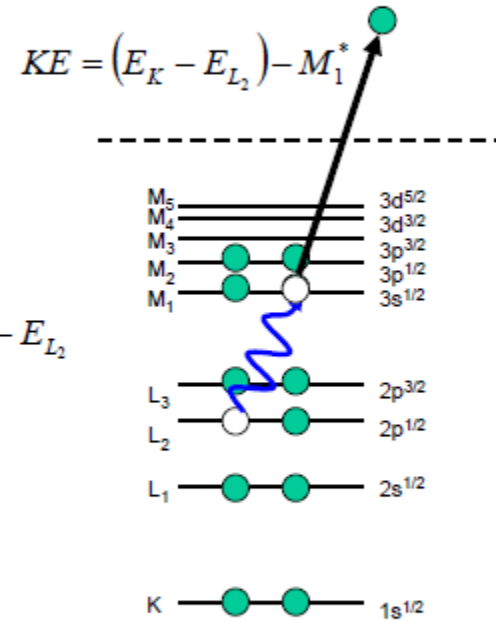
2a) X-ray Emission



Measured by EDS/XRF

(X-ray fluorescence in an SEM or TEM)

2b) Auger electron

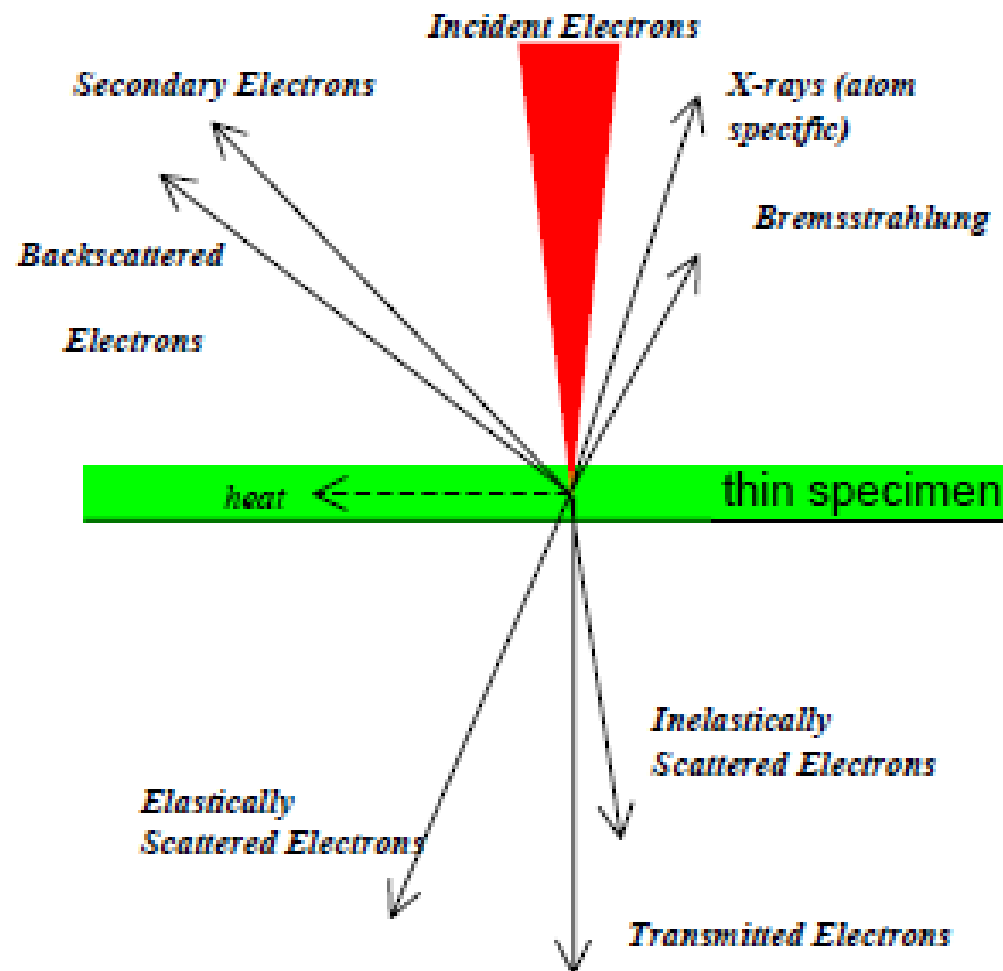


Measured by AES

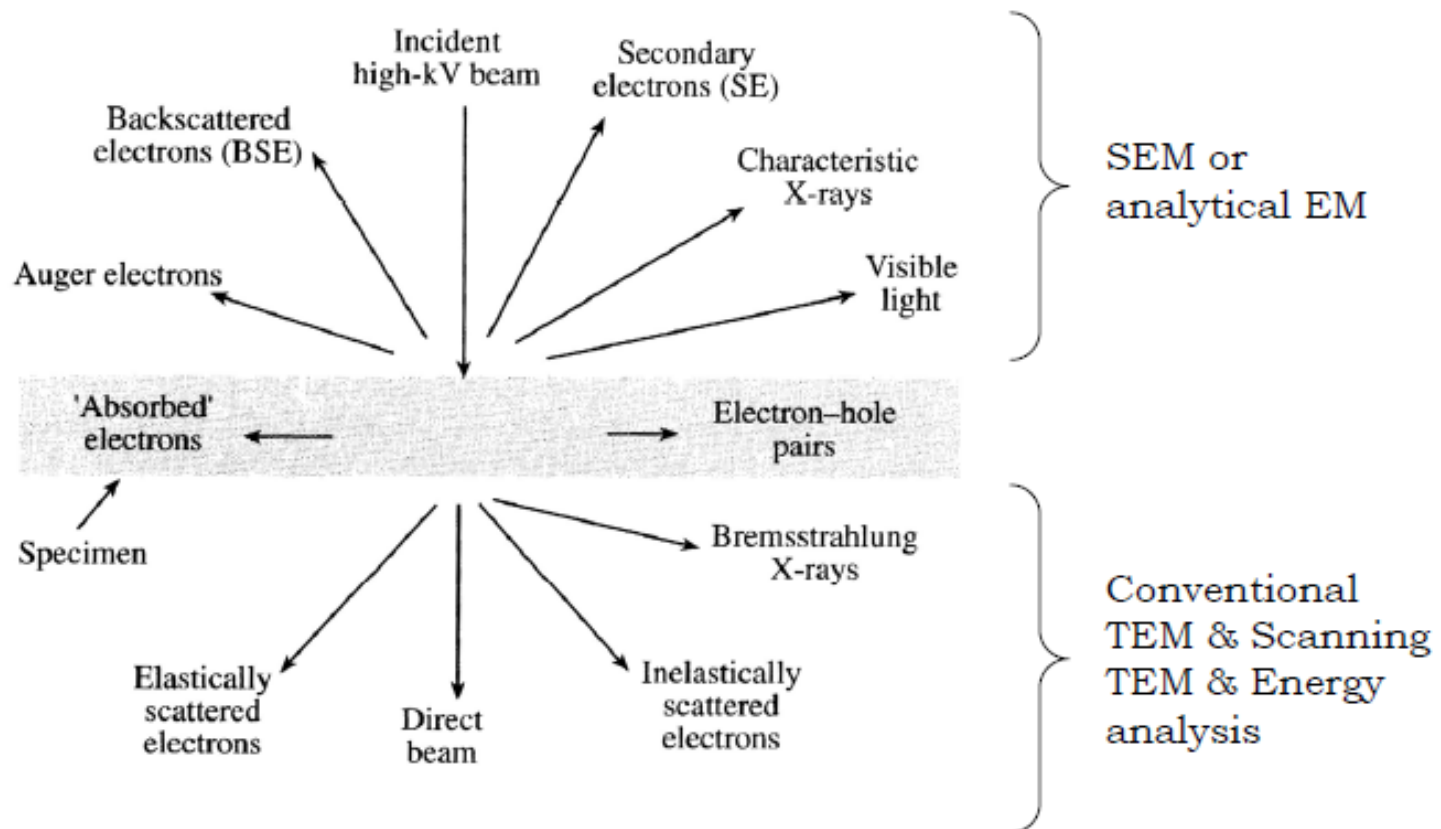
(Auger Spectroscopy in a SAM,
Leaves atom doubly charged)

Interaction of high energy (\sim kV) electrons with (solid) materials-II

Interaction with a thin specimen (TEM & STEM)



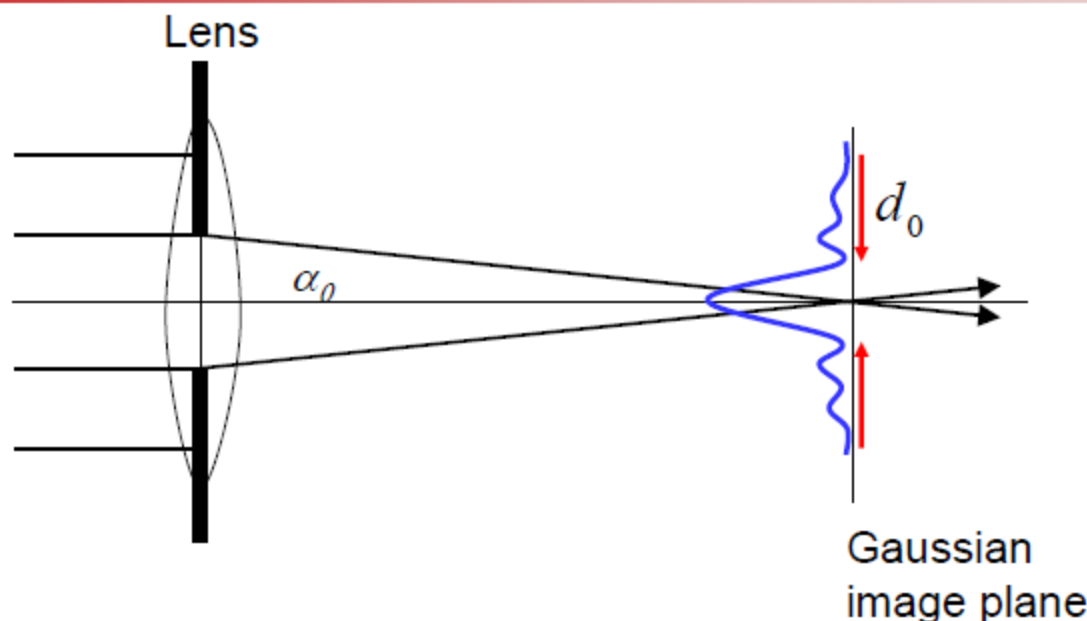
Interaction of Electron with Samples



Resolution Limits Imposed by the Diffraction Limit



(Less diffraction with a large aperture – must be balanced against C_s)



The image of a point transferred through a lens with a circular aperture of

semiangle α_0 is an Airy Disk of diameter $d_0 = \frac{0.61\lambda}{n \sin \alpha_0} \approx \frac{0.61\lambda}{\alpha_0}$

(0.61 for incoherent imaging e.g. ADF-STEM, 1.22 for coherent or phase contrast, E.g TEM)

Electron Velocity and Wavelength



De Broglie Wavelength: $\lambda = \frac{h}{p}$ Where h is Planck's constant
And $p=mv$ are the momentum,
mass and velocity of the electron

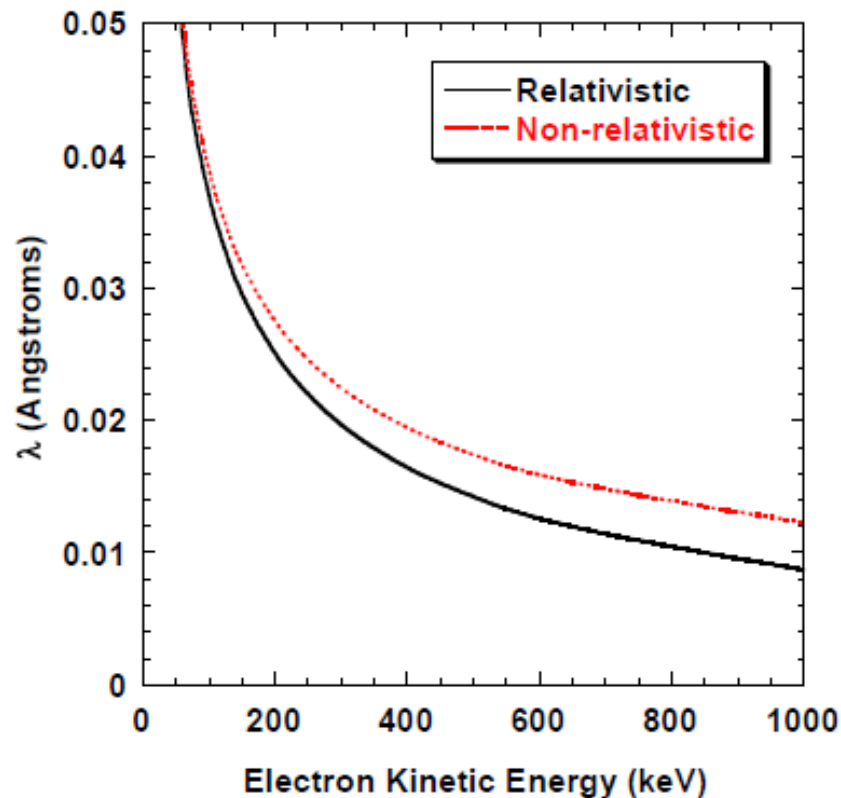
If an electron is accelerated through a potential eV , it gains kinetic energy

$$\frac{1}{2}mv^2 = eV \quad \text{So the momentum is} \quad mv = \sqrt{2meV}$$

$$\text{Electron wavelength } \lambda = \sqrt{\frac{h^2}{2meV}} = \frac{1.23\text{nm}}{\sqrt{V}} \quad (\text{V in Volts})$$

$$(\text{ relativistically correct form: } \lambda = \sqrt{\frac{h^2 c^2}{eV(2m_0 c^2 + eV)}})$$

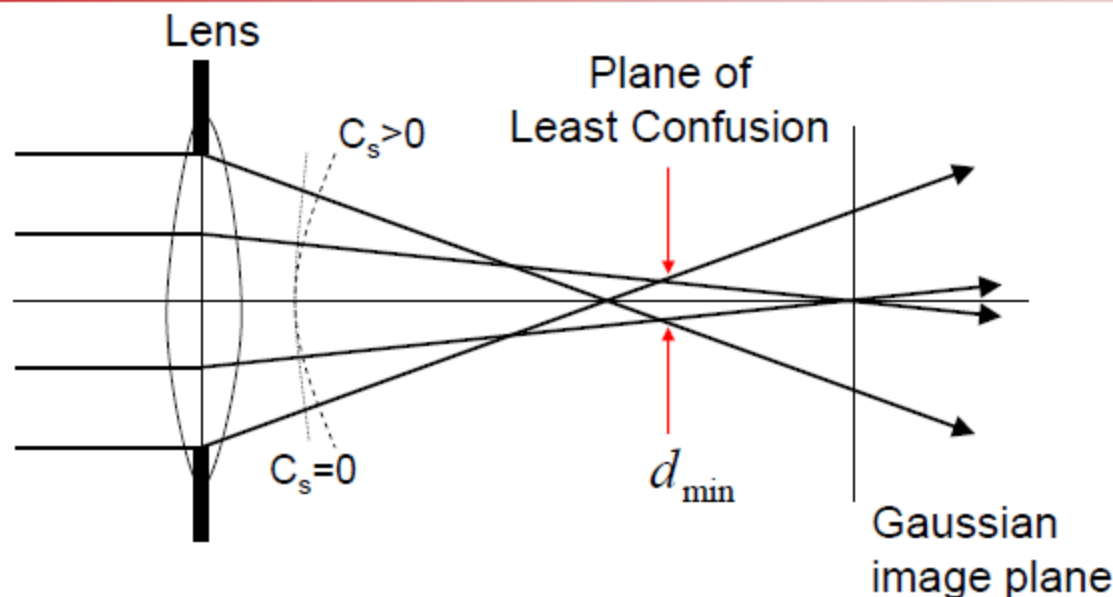
Electron Wavelength vs. Accelerating Voltage



Accelerating Voltage	v/c	λ (Å)
1 V	0.0019784	12.264
100 V	0.0062560	1.2263
1 keV	0.062469	0.38763
10 keV	0.019194	0.12204
100 keV	0.54822	0.037013
200 keV	0.69531	0.025078
300 keV	0.77653	0.019687
1 MeV	0.81352	0.0087189

Resolution Limits Imposed by Spherical Aberration, C_s

(Or why we can't do subatomic imaging with a 100 keV electron)



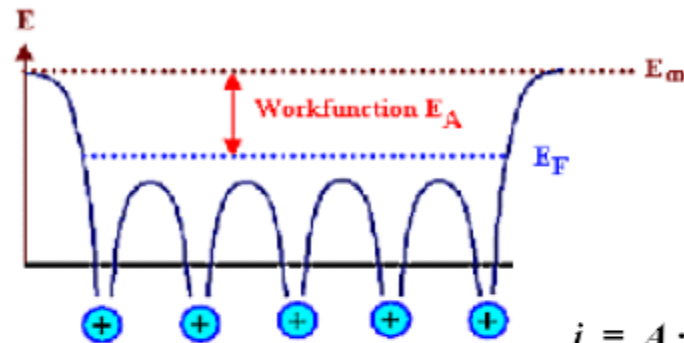
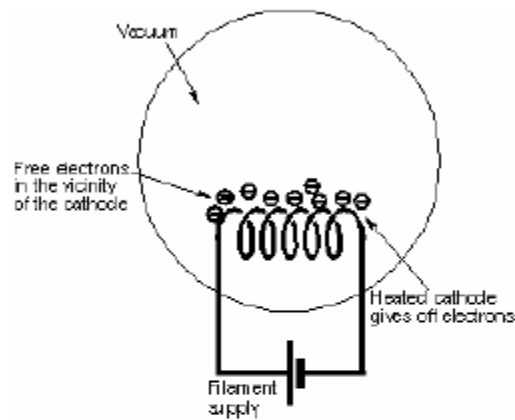
For $C_s > 0$, rays far from the axis are bent too strongly and come to a crossover before the gaussian image plane.

For a lens with aperture angle α , the minimum blur is
$$d_{min} = \frac{1}{2} C_s \alpha^3$$

Typical TEM numbers: $C_s = 1 \text{ mm}$, $\alpha = 10 \text{ mrad} \rightarrow d_{min} = 0.5 \text{ nm}$

Electron sources

- Thermal emission

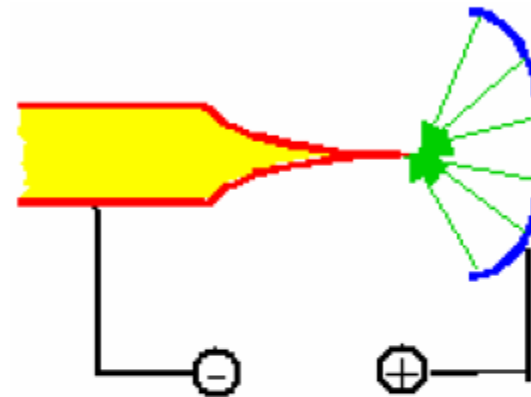
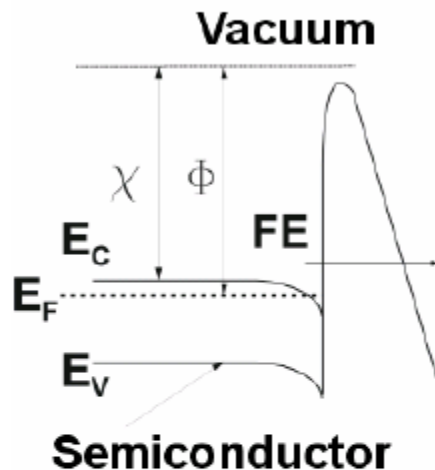


$$j = A \cdot T^2 \cdot \exp - \frac{E_A}{kT}$$

Material	Fe	Ni	Pt	Ta	W	Cs	LaB ₆
A [Acm ⁻² K ⁻²]	26	30	32	55	60	162	25
E_A [eV]	4,5 - 4,8	5,15 - 5,35	5,65	4,15 - 4,8	4,2	1,8 - 2,14	2,6
T_m [°C]	1 535	1 452	1 755	2 850	3 410	28,4	2 210

Electron sources

- Field emission



Field emission starts for $E > 10^7$ V/cm

High current density: $J(E) = A \cdot E^2 \phi \exp(-B \phi^{1.5} / E)$

Strong nonlinear current-voltage characteristic

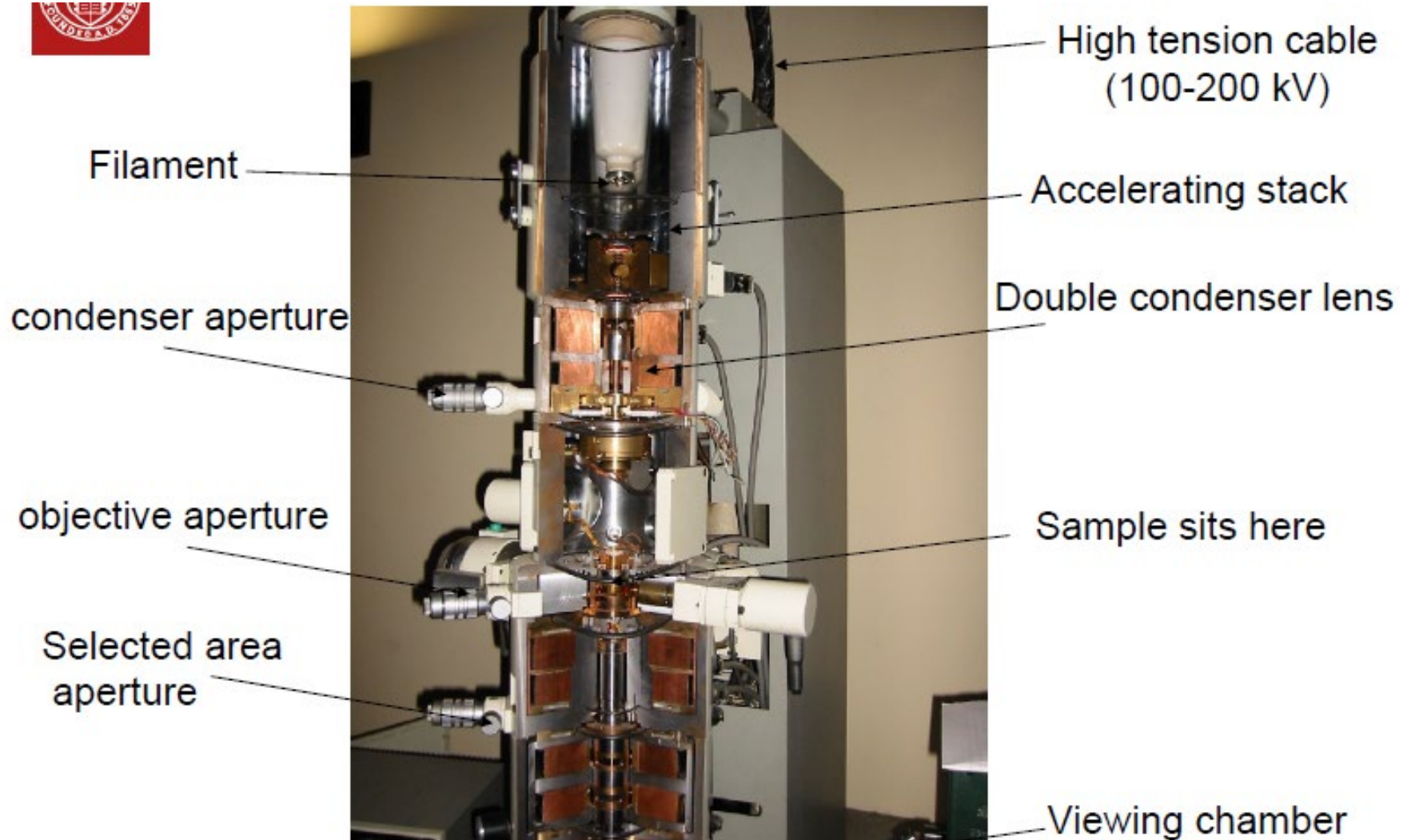
Very short switching time ($t < ns$)

Small spot size due to field enhancement at the tip apex

- Electron beam sources

TABLE 2.1 Properties of the electron sources commonly used in electron beam lithography tools.

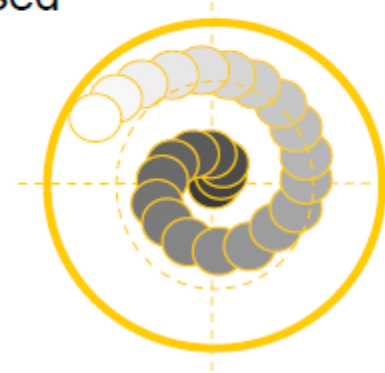
source type	brightness (A/cm ² /sr)	source size	energy spread (eV)	vacuum requirement (Torr)
tungsten thermionic	$\sim 10^5$	25 μ m	2-3	10^{-6}
LaB ₆	$\sim 10^6$	10 μ m	2-3	10^{-8}
thermal (Schottky) field emitter	$\sim 10^8$	20 nm	0.9	10^{-9}
cold field emitter	$\sim 10^9$	5 nm	0.22	10^{-10}



Lenses

- Provide means to (de)focus the electron beam on the specimen, to focus the image, to change the magnification, and to switch between image and diffraction

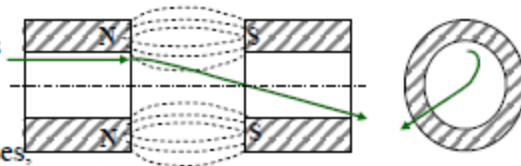
- Electromagnetic lenses are based on the fact the moving electrons are forced into a spiral trajectory, i.e. focused into one point



Round Lenses

Magnetic lenses

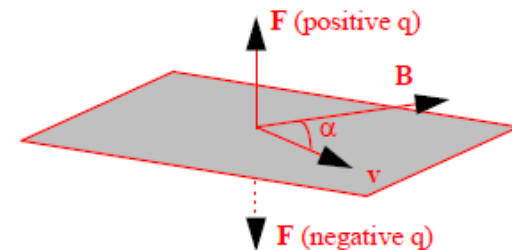
- ▶ change the direction of electrons
- ▶ magnifying (diverging)
- ▶ diminishing (converging)
- ▶ condenser lenses, objective lenses, intermediate lenses, projection lenses



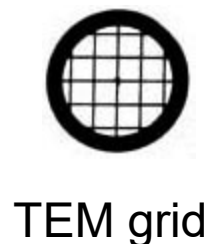
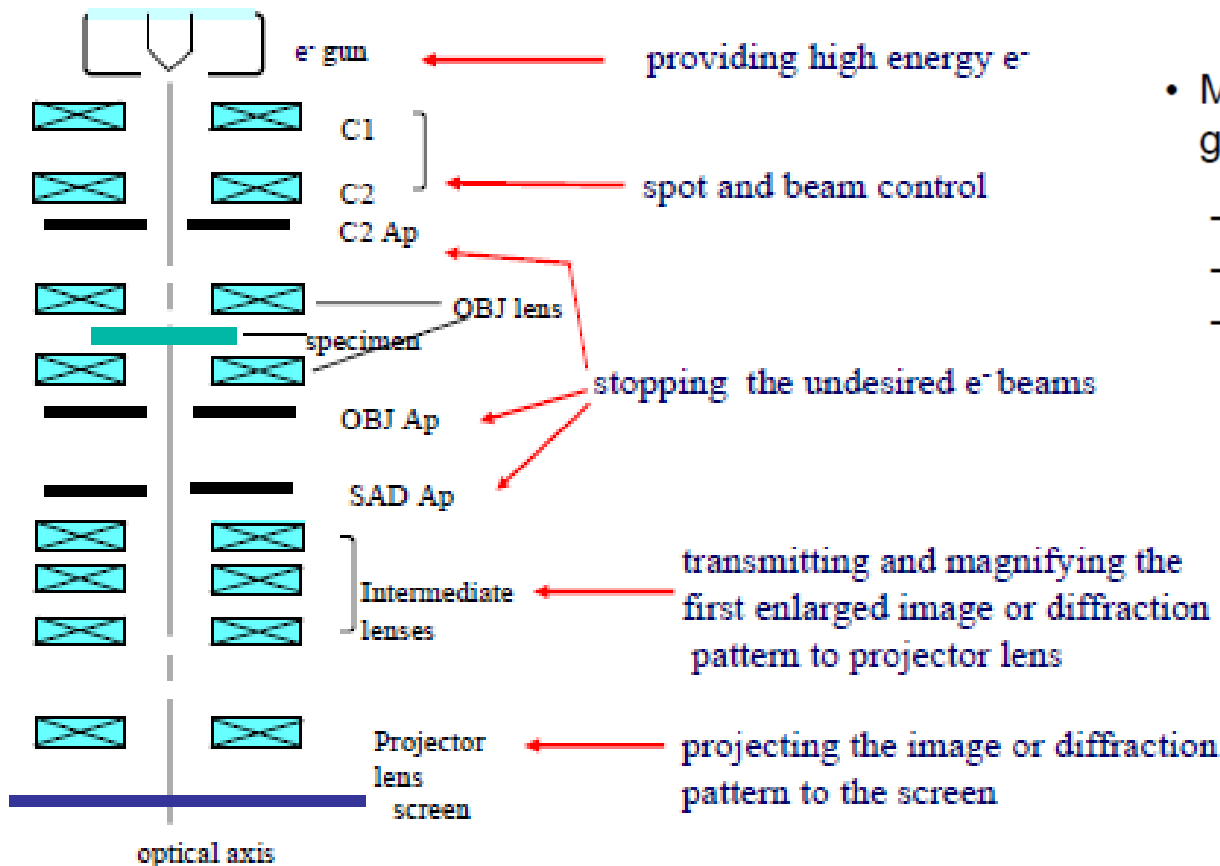
- Working Principle: Lorentz Force
 - electrons are only *deflected* by magnetic fields

Electrostatic lenses: the Wehnelt cap

- Advantage
 - ▶ rotation free
- Disadvantage
 - ▶ high precision in construction
 - ▶ high precision in alignment
 - ▶ extreme cleanliness



Lens System of TEM



Lens System & Microscope Resolution

- Microscope resolution is governed by: (for TEM)
 - wavelength of electrons
 - C_s of objective lens
 - other lenses are less crucial (α/M)

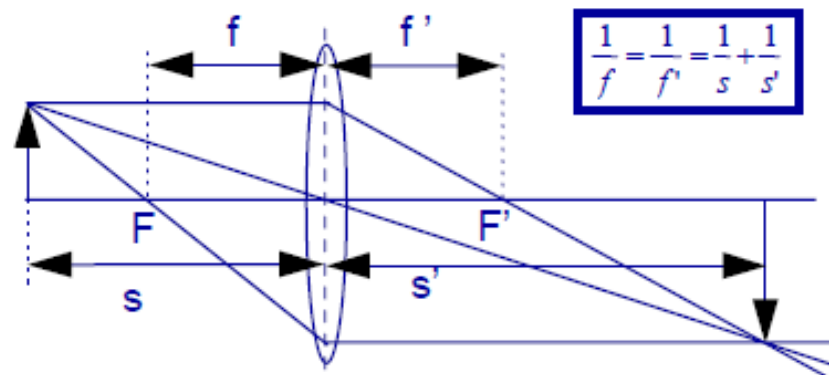
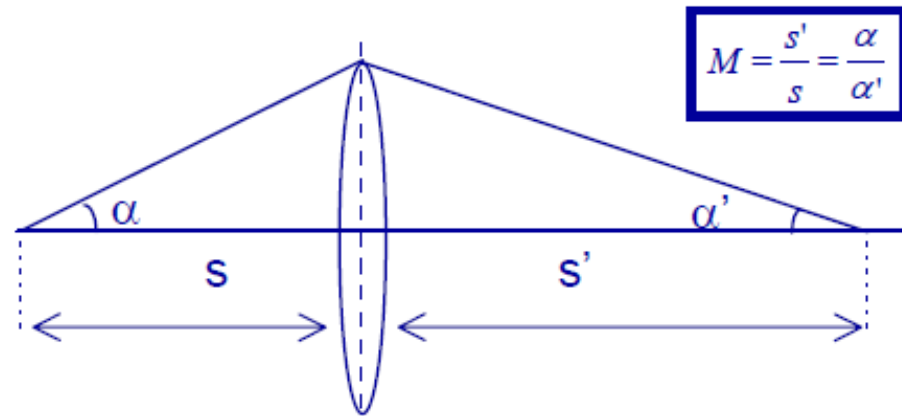
$$\delta = 0.66 \times C_s^{1/4} \lambda^{3/4}$$

Electron Detectors

- TEM
 - phosphor screen, Film, CCD, Image Plate...
- SEM
 - SE detector, BE detector....
- STEM
 - BF detector, DF detector,

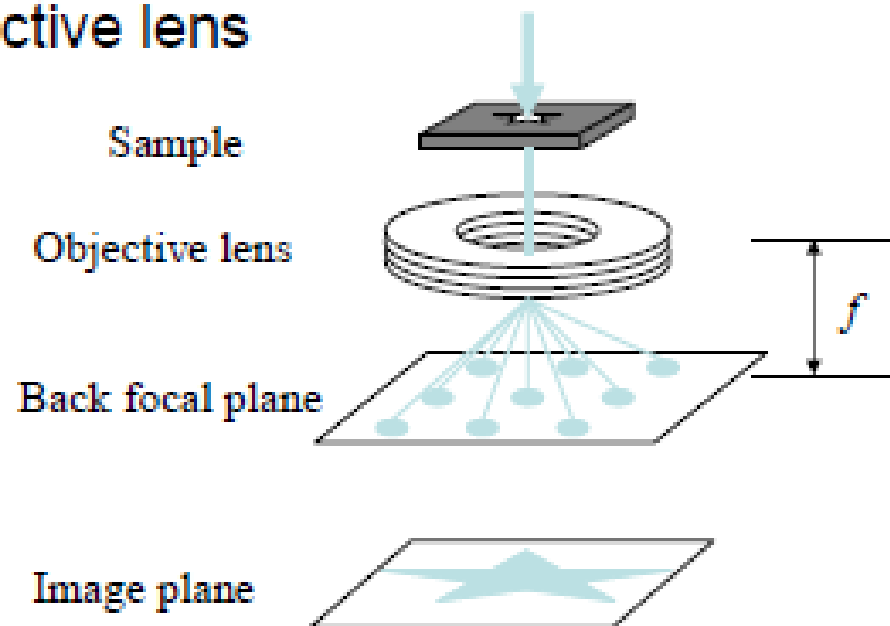
Geometric (ray) optics

- Gaussian Law



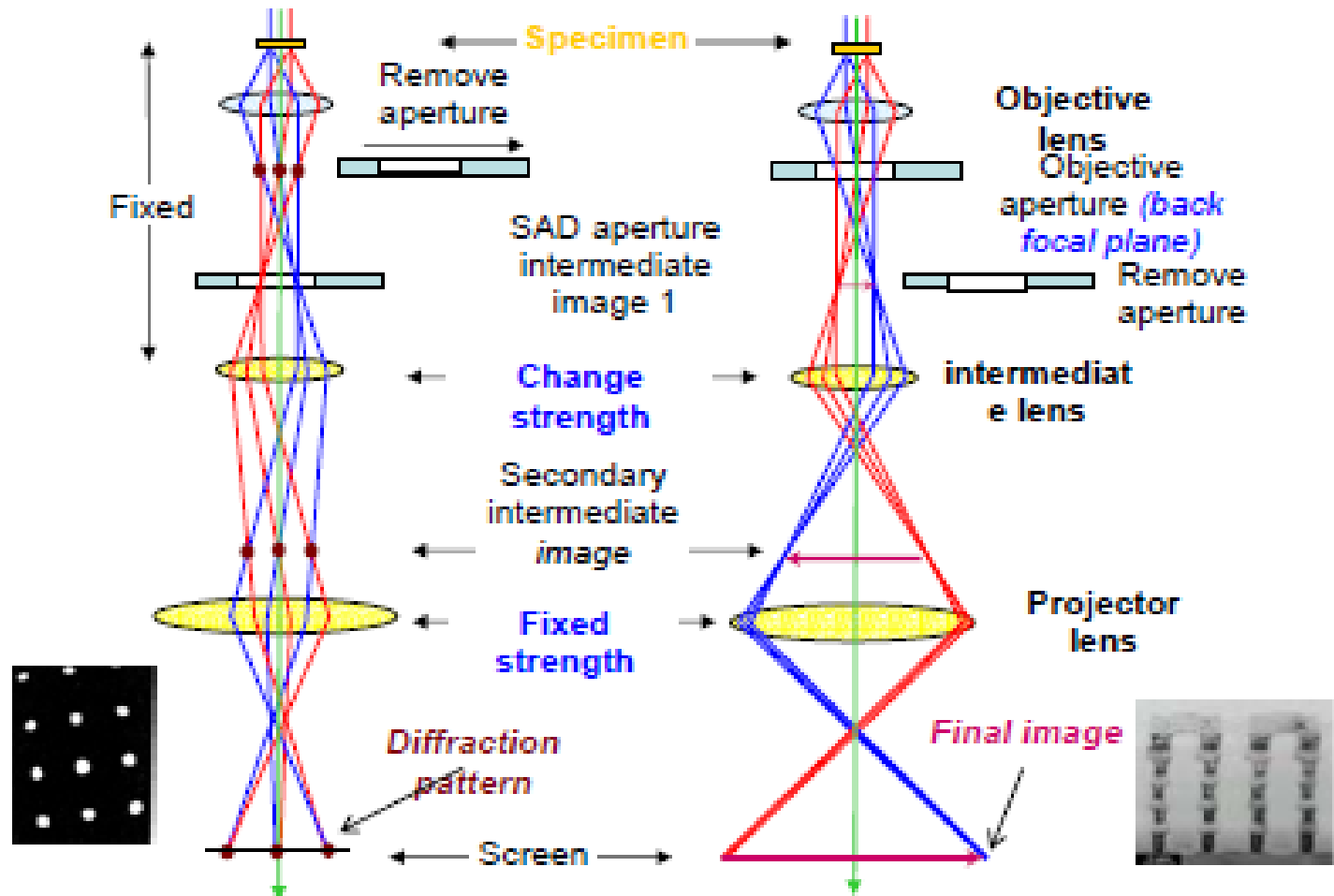
Electron diffraction

- Diffraction pattern locates at the back focal plane of the objective lens



Diffraction mode

Image mode



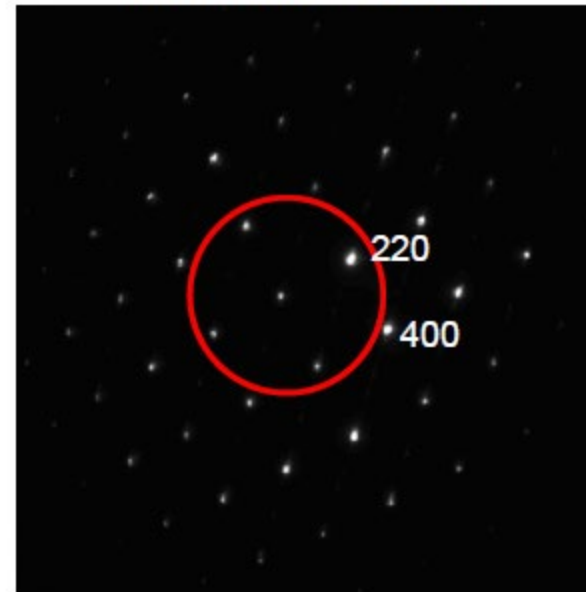
Electron Diffraction and Imaging a [100] Silicon Crystal



Image



Diffraction Pattern



$$\lambda = 0.0251 \text{ \AA}$$

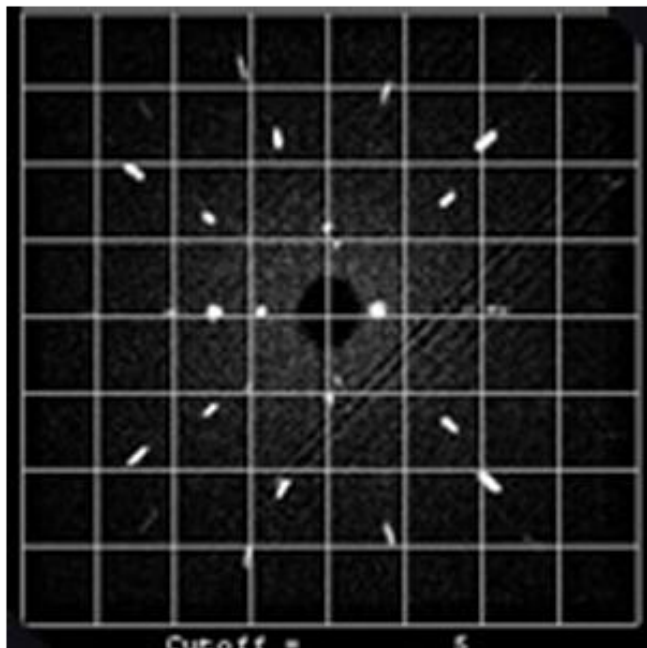
$$\text{In Si } d_{220} = 1.92 \text{ \AA}$$

X-ray and Electron Diffraction from a Silicon Crystal



Bragg's Law: $n\lambda = 2d \sin \theta$

10 keV x-rays



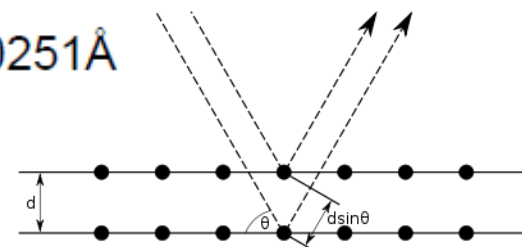
$\lambda = 1.54 \text{ \AA}$

200 keV Electrons



$\lambda = 0.0251 \text{ \AA}$

In Si $d_{220} = 1.92 \text{ \AA}$



Spot pattern

- Single crystal within the illumination area
- The regular arrangement of spots
- Spot brightness relates to the structure factor
- Spot position relates to the d-spacing

$$F_{hkl} = \sum_i f_i e^{2\pi i(hx_i + ky_i + lz_i)}$$

for fcc, the basis vector is

$$(x, y, z) = (0, 0, 0), \left(\frac{1}{2}, \frac{1}{2}, 0\right), \left(\frac{1}{2}, 0, \frac{1}{2}\right), \left(0, \frac{1}{2}, \frac{1}{2}\right)$$

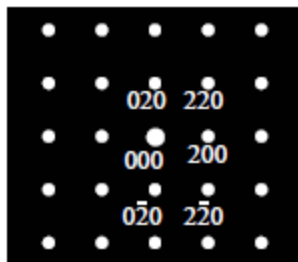
$$\text{so } F = f \{1 + e^{\pi i(h+k)} + e^{\pi i(h+l)} + e^{\pi i(k+l)}\}$$

$$F = 4f, \text{ if } h, k, l \text{ are all even or all odd}$$

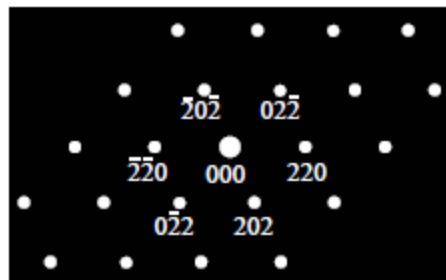
$$F = 0, \text{ if } h, k, l \text{ are mixed even and odd}$$

hkl – Miller indices

- Example 1: f.c.c

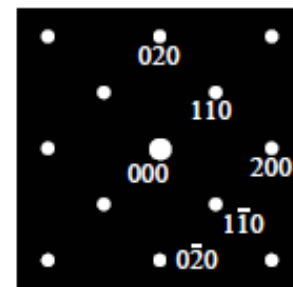


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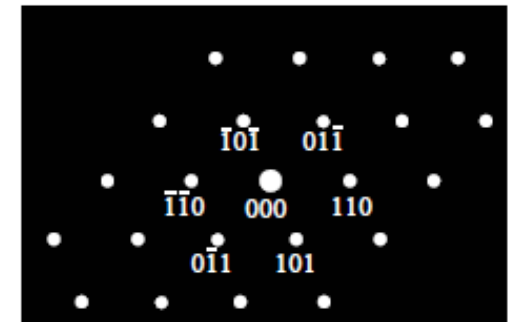


[111]

- Example 2: b.c.c

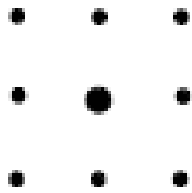
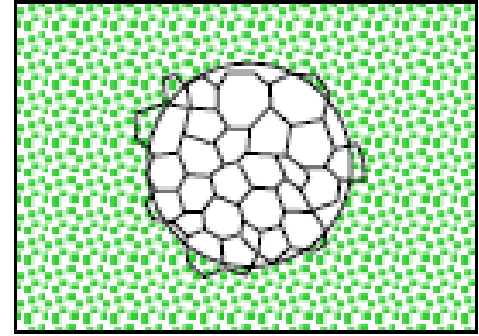
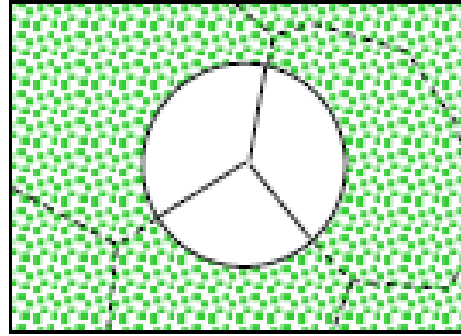
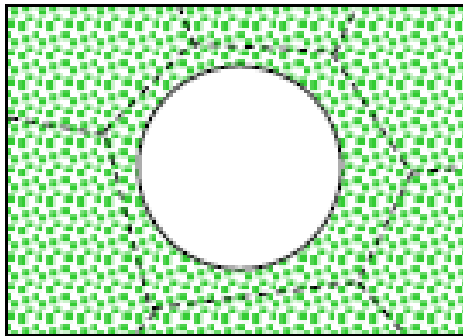


[001]

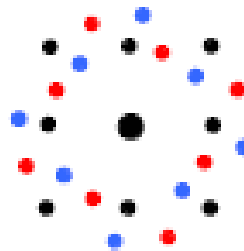


[111]

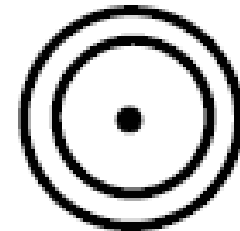
Electron Diffraction Pattern--Spot to Ring



(a)

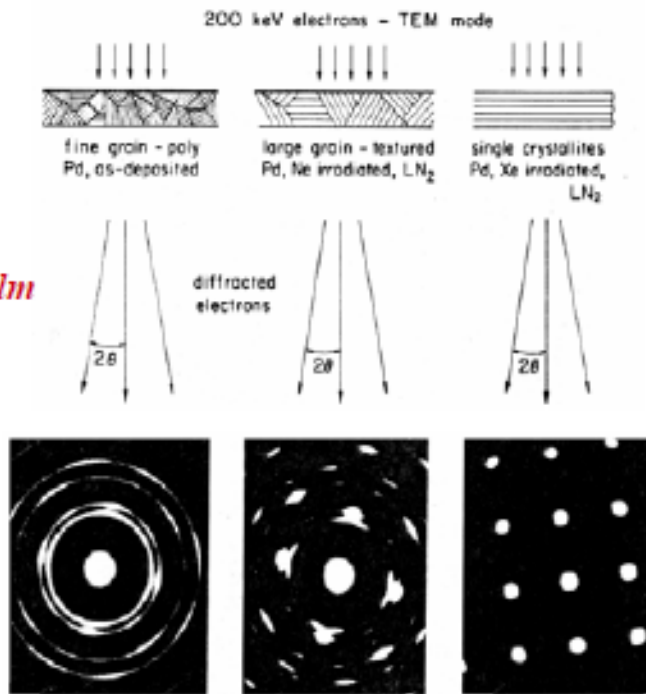


(b)



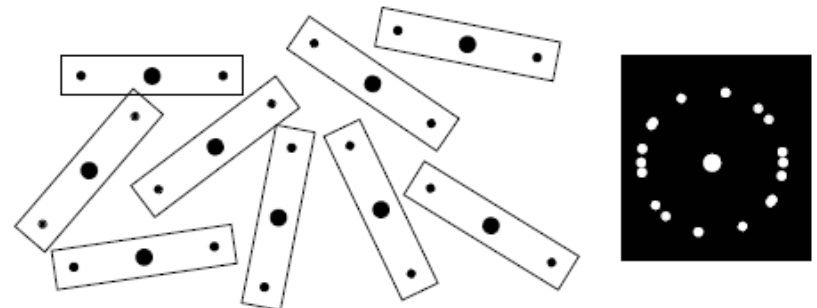
(c)

*Electron Beam
Diffraction of a Pd film*



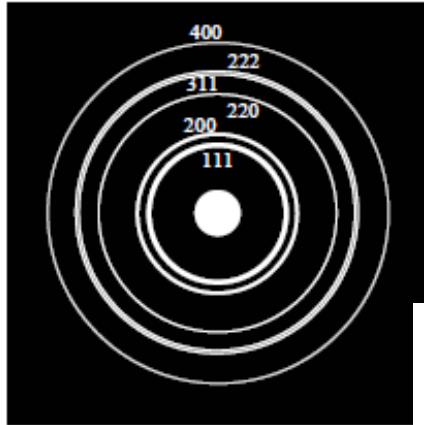
Ring pattern

- Many fine particles in the illumination area, each of them is a single crystal and orientated randomly



Ring pattern

- Typical polycrystalline Au diffraction pattern



Ring pattern: what can we obtain

- d-spacing

$$2Rd_{hkl} = L\lambda$$

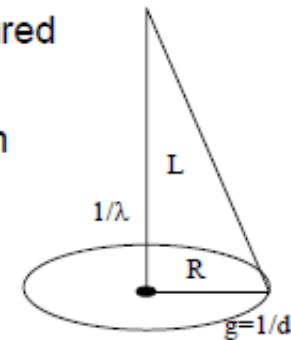
R: the measured ring radius

d_{hkl} : the d-spacing being measured

L: camera length

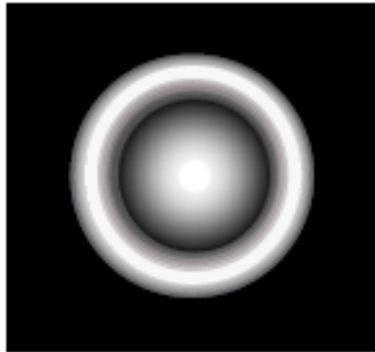
λ : wave length of electron beam

- Camera length calibration
- Crystalline / particle fineness

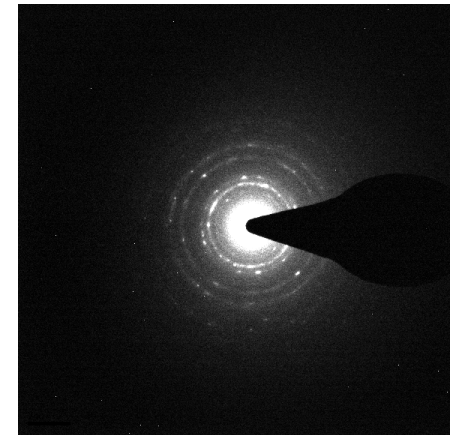
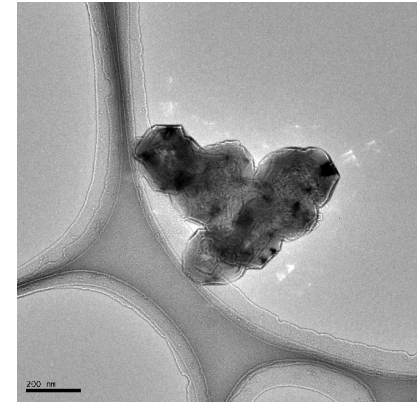


Amorphous materials

- Diffused ring pattern
- Reflecting the short range ordered structure
- Often seen at contamination layer or on carbon support film

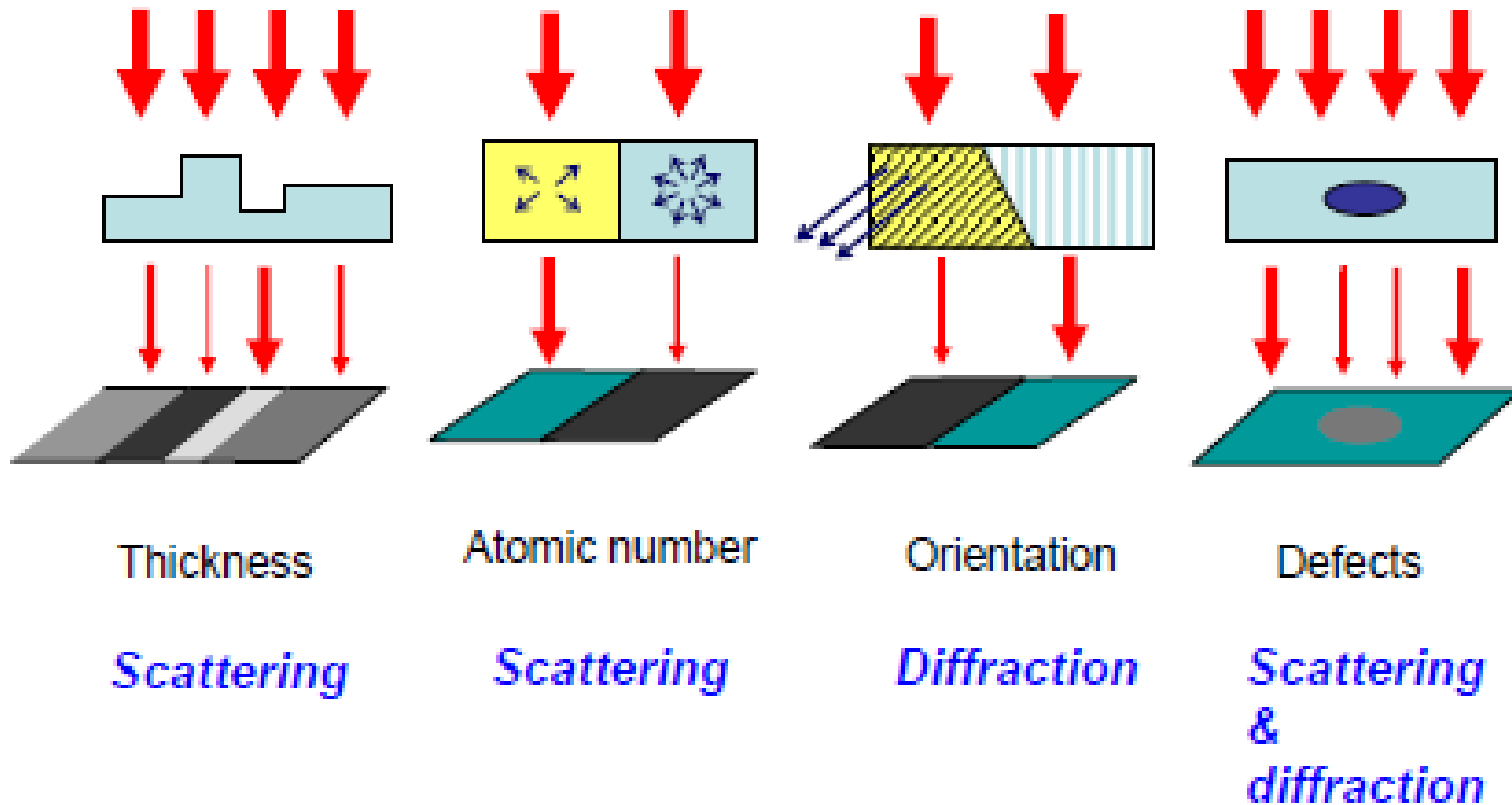


ADT-TES-F



d-spacings: 1.26 – 3 Å

Major Factors affecting TEM Image Contrast



Four-Dimensional Electron Microscopy

Ahmed H. Zewail

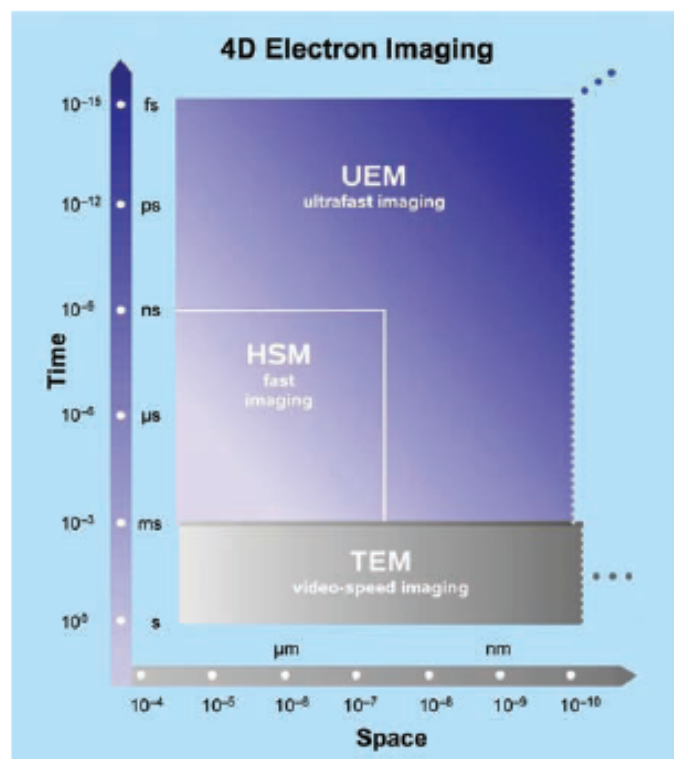


Fig. 1. 4D electron imaging. The resolution boundaries of ultrafast imaging are compared with those achieved in conventional TEM, limited by the speed of video camera, and, in high-speed microscopy (HSM), defined by the rectangle shown. The spatio-temporal scales of UEM achieved to date are outlined with possible future extensions. The approaches of single-electron and single-pulse imaging are fundamentally different because of the limiting problem of space-charge described in the text.

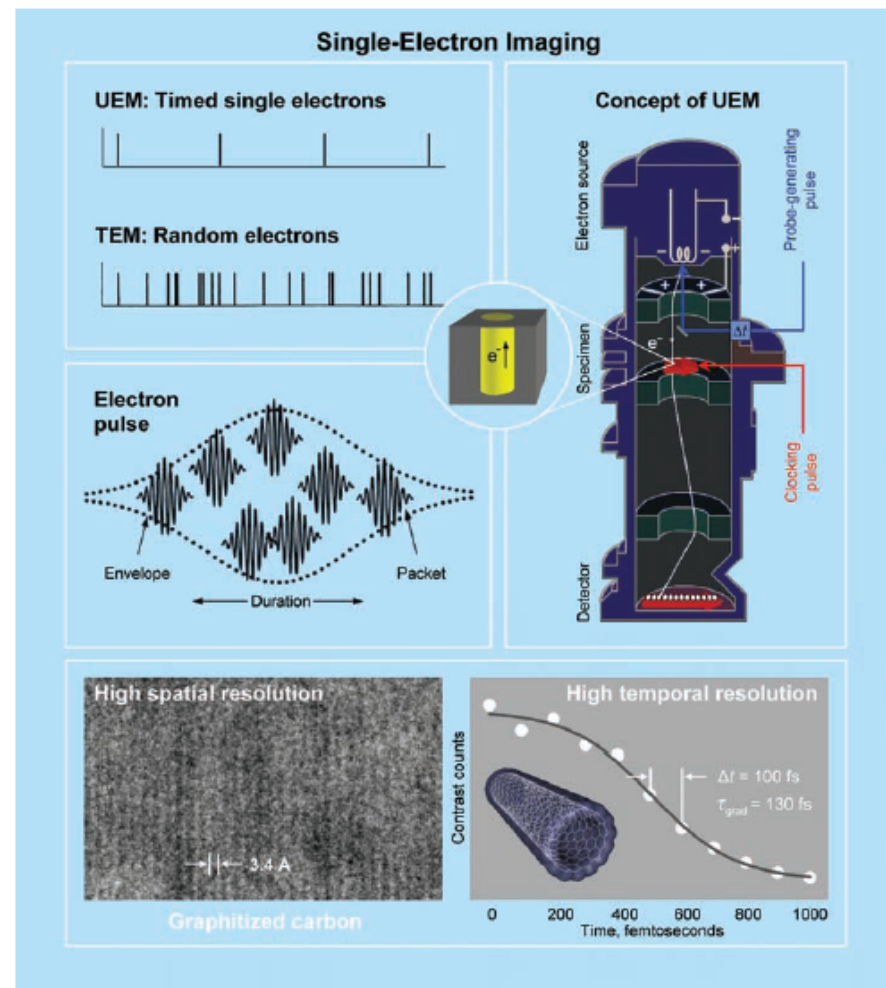


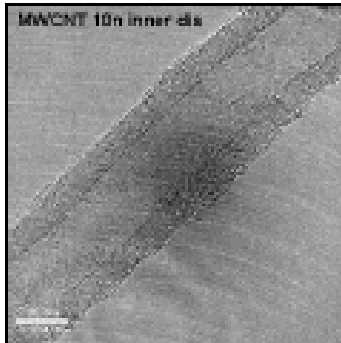
Fig. 2. Conceptual and experimental realization of single-electron imaging. Shown are schematics of timed single-electron packets (UEM) and random electrons (conventional TEM) used in imaging (upper left). Also depicted is the electron-pulse envelope together with individual electron packets (center left). A single-electron trajectory is schematized in the microscope together with an illustration of what is meant by a coherence volume (upper right; see text). The bottom panel displays a high-resolution UEM image of graphitized carbon with lattice-plane separations of 3.4 Å (left), and a temporal profile obtained from the images of evanescent fields in carbon nanotubes; the time steps are of 100-fs duration, and the rate of change is given by the gradient ($\tau_{\text{grad}} = 130$ fs), which is determined by the materials response and pulse widths involved (see the section on near-field UEM and Fig. 5). The experimental data are from (10, 46).

Scanning Electron Microscope

- Sequential imaging similar to the optical scanning confocal microscope
- Can be used in reflection or transmission modes (STEM)

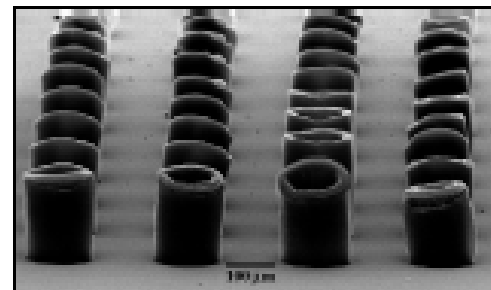
TEM

- Resolution: atomic
- Can determine 3-D structure
- Be careful of e^- - e^- interactions



SEM

- Resolution: atomic
- Surface features
- Requires Vacuum
- Often must coat specimens



NASA nanotech group

SEM capabilities

Topography

The surface features of an object or "how it looks", its texture;
direct relation between these features and materials properties

Morphology

The shape and size of the particles making up the object; direct
relation between these structures and materials properties

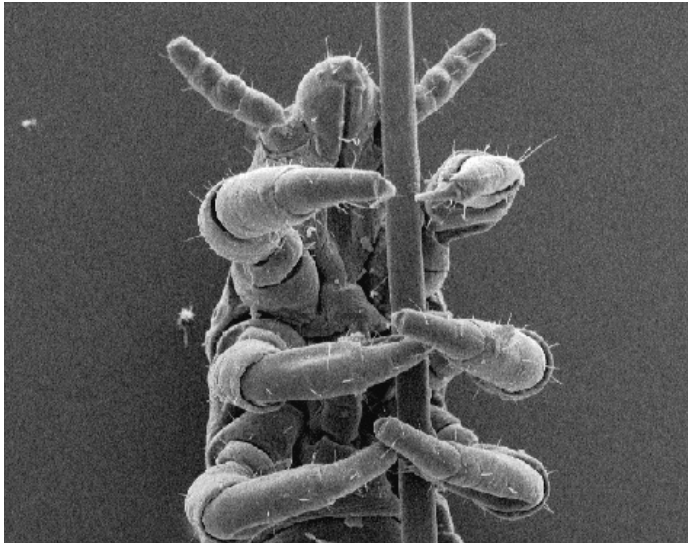
Composition

The elements and compounds that the object is composed of
and the relative amounts of them; direct relationship between
composition and materials properties

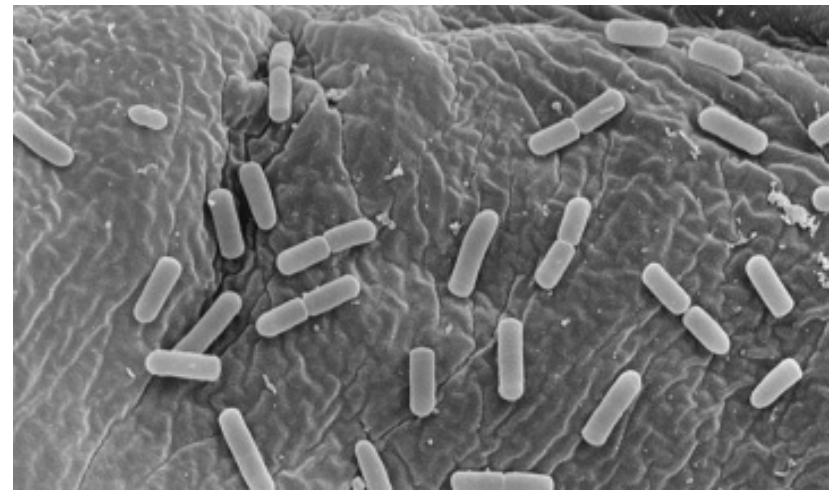
Crystallographic Information

How the atoms are arranged in the object; direct relation
between these arrangements and material properties

Some SEM images



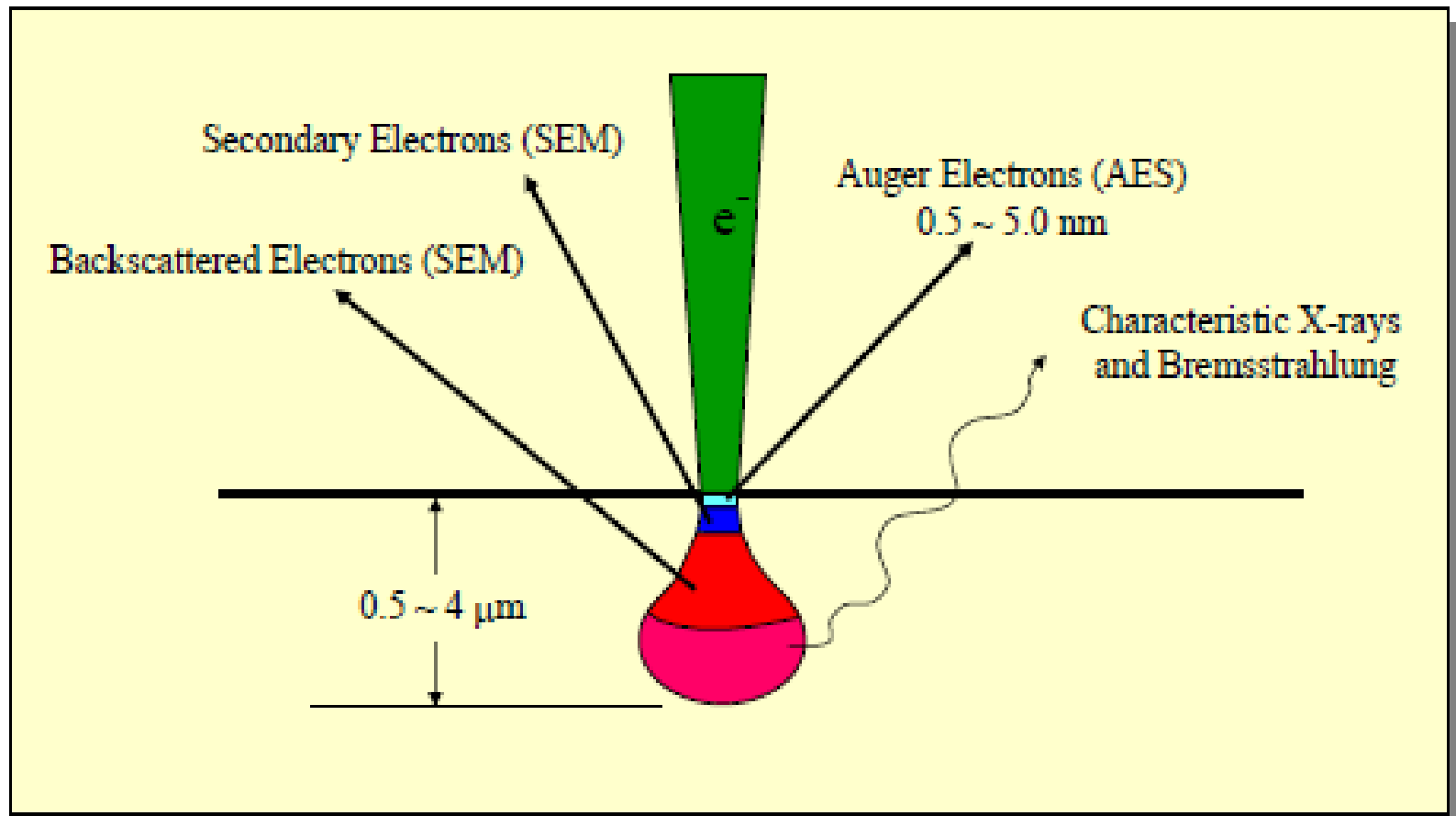
Insect climbing up a straw



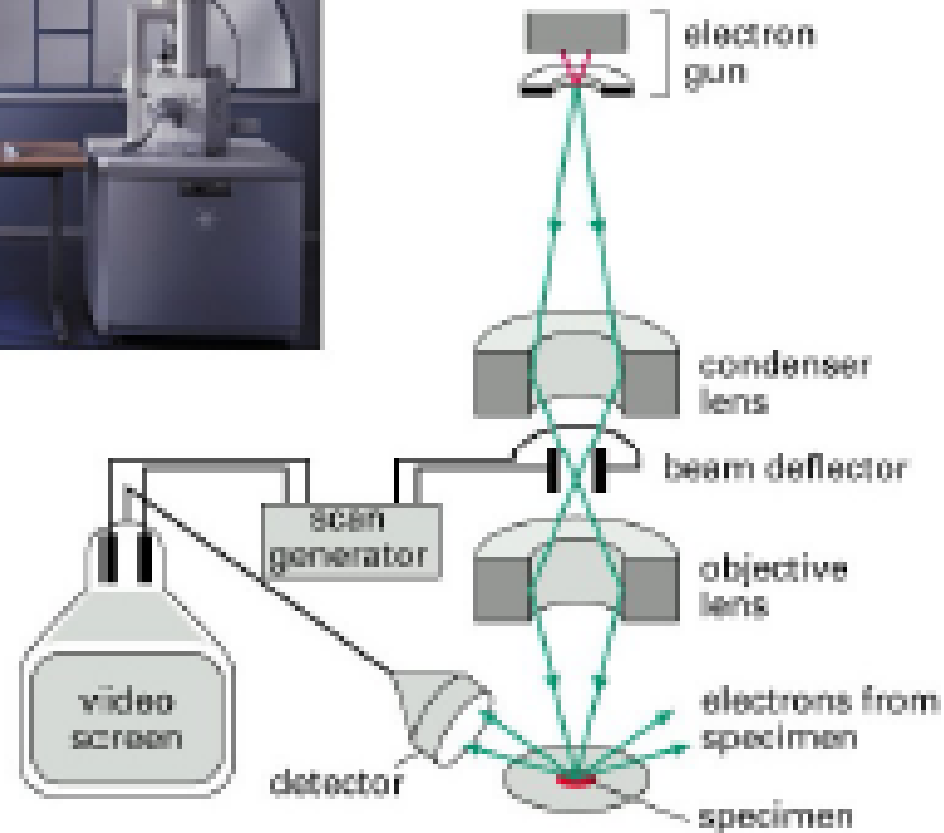
bacteria distributed over the surface of shredded lettuce leaf at the end of its shelf life

Interaction of high energy (\sim kV) electrons with (solid) materials-III

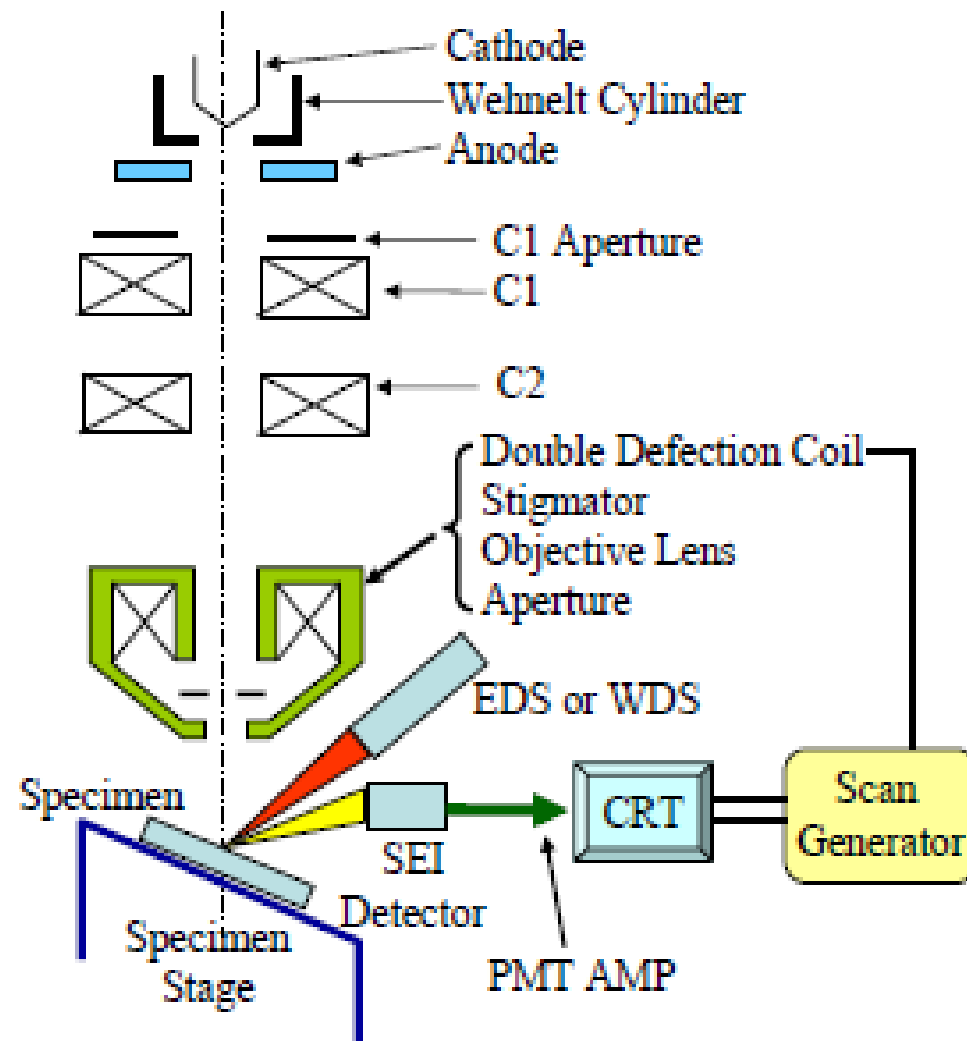
Interaction with a thick specimen (SEM)



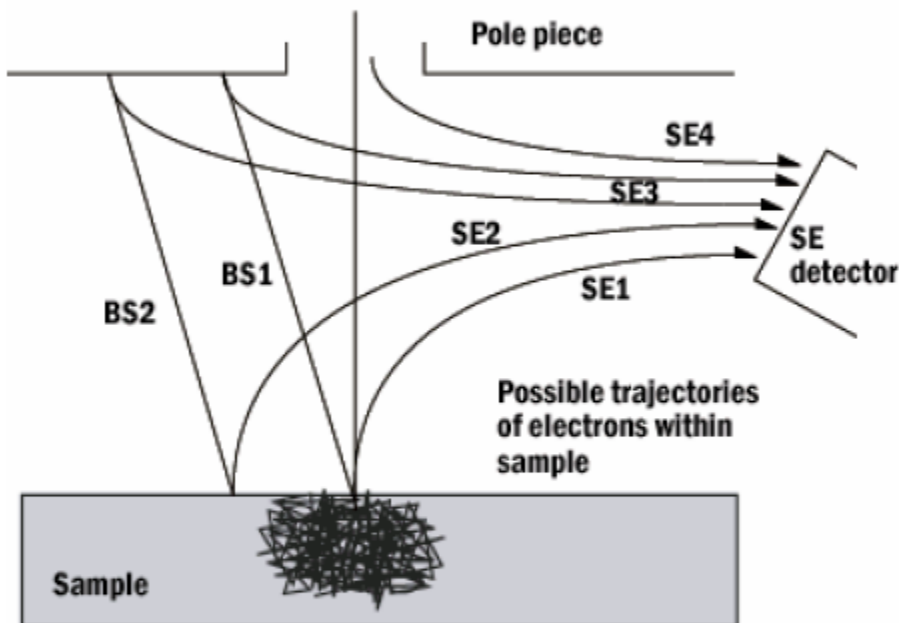
Scanning Electron Microscope



Lens System of SEM

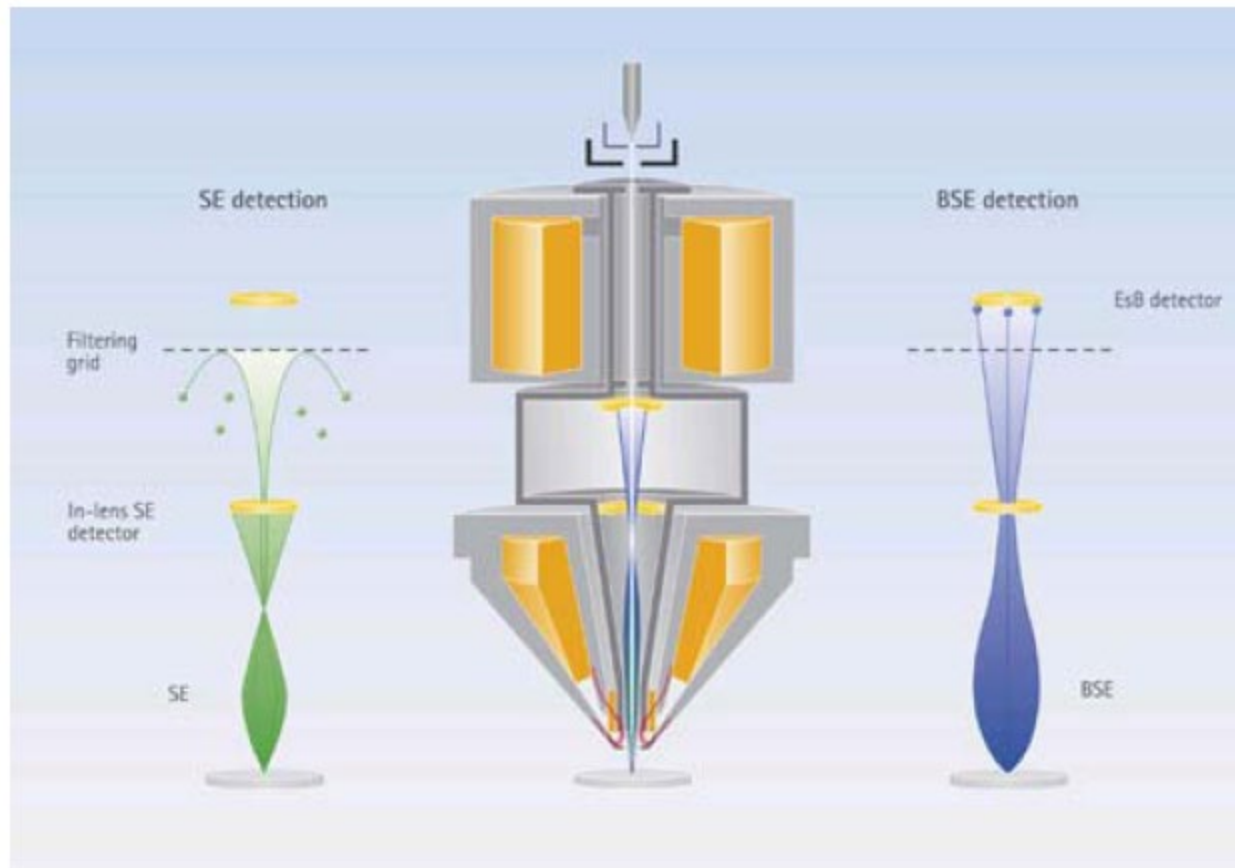


Detectors: Secondary Elec. Det.



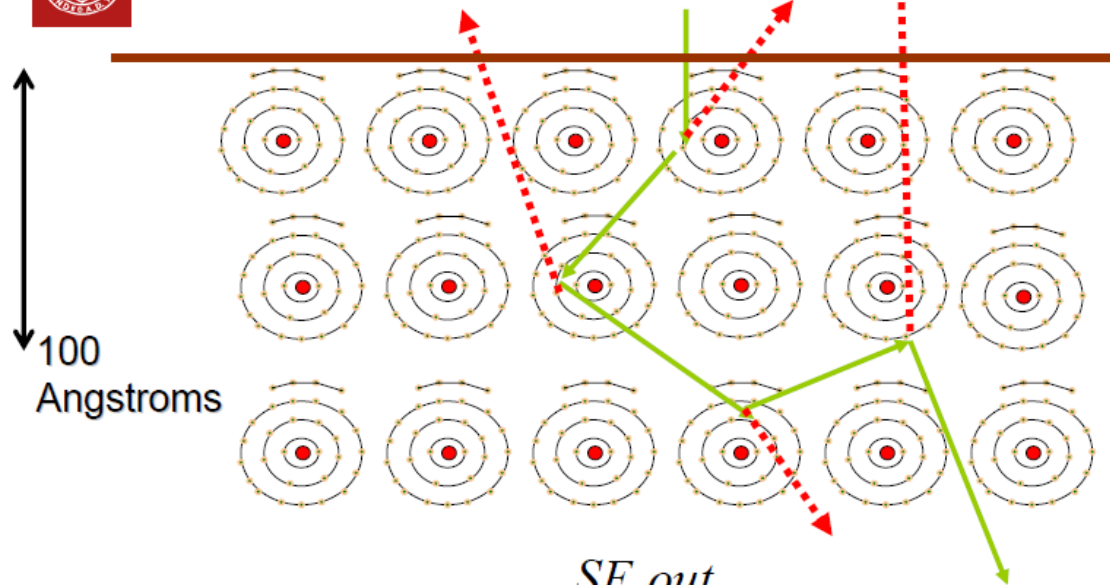
- Secondary electrons generally low energy (50-100 eV)
- Trajectories can be bent easily by biasing the detector
- Low Z contrast

Energy filtered detection of electrons



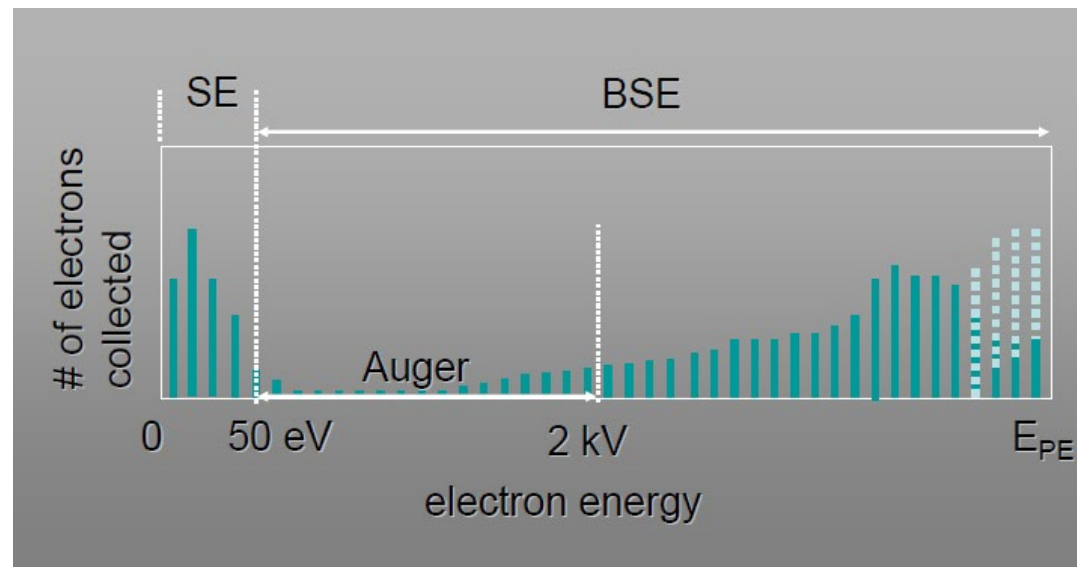


One Primary Electron In Can Create Several SEs Out at Low Accelerating Voltages



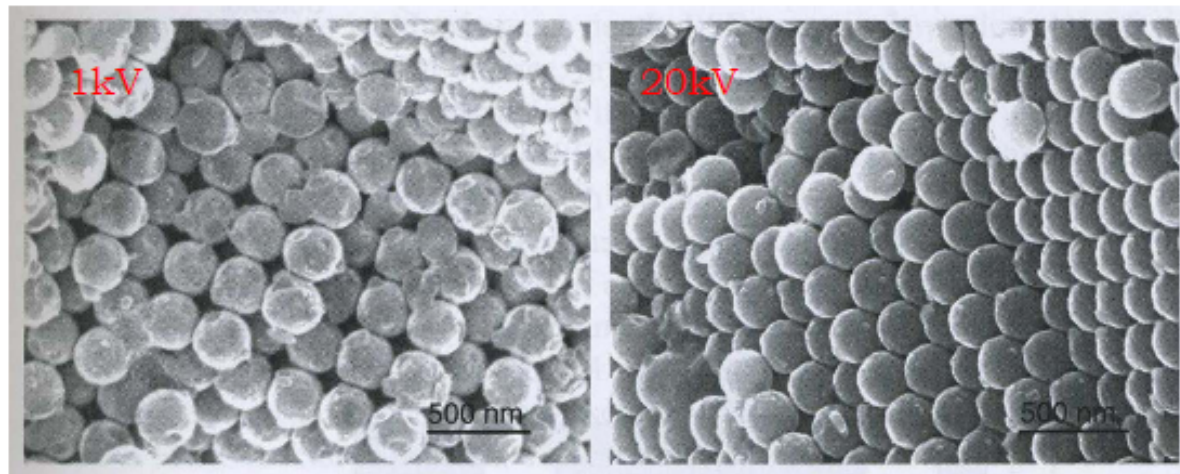
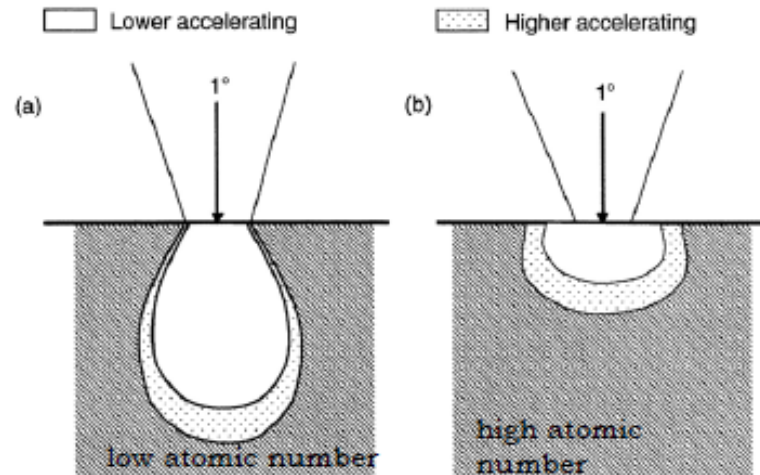
Secondary Electron
Yield Coefficient

$$\delta = \frac{SE\ out}{PE\ in}$$



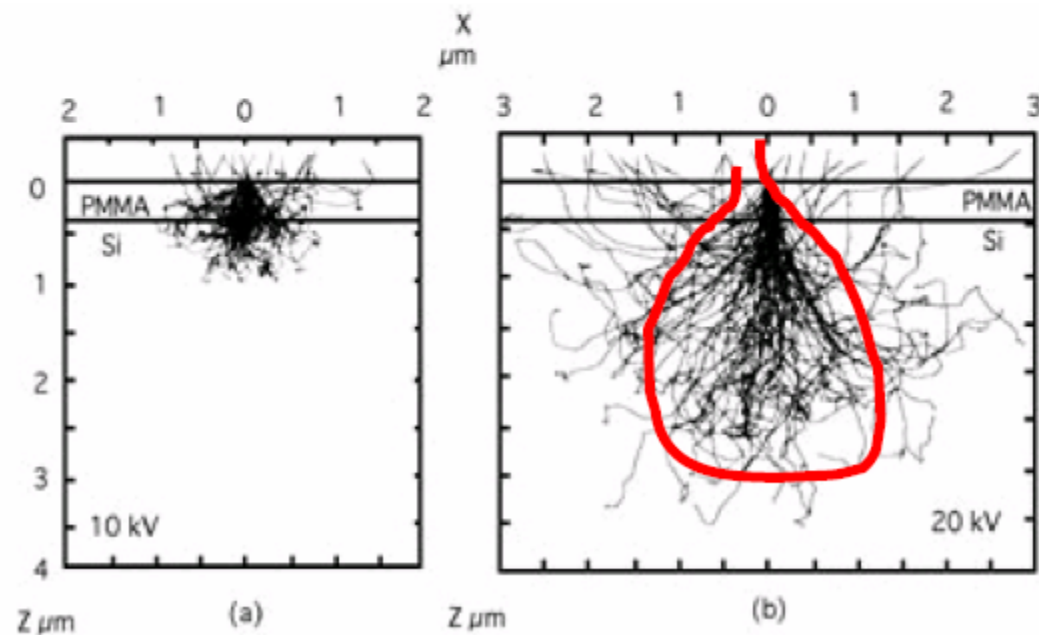
Secondary electrons

- Low energy
- Topographic contrast (surface texture and roughness)
- Resolve surface structure down to 10nm
- Excitation region depends on the accelerating voltage

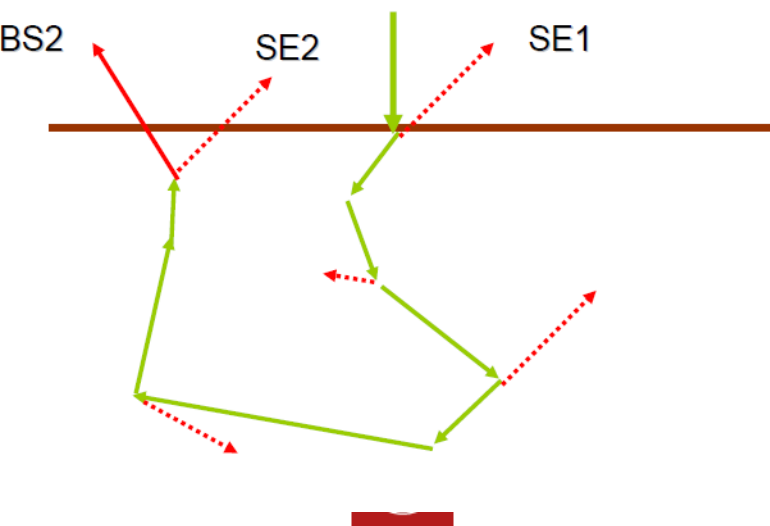


Electron Beam and Sample Interaction

- Depends on energy of beam, material of the sample. The beam penetrates the sample
- Beam Spot size isn't everything



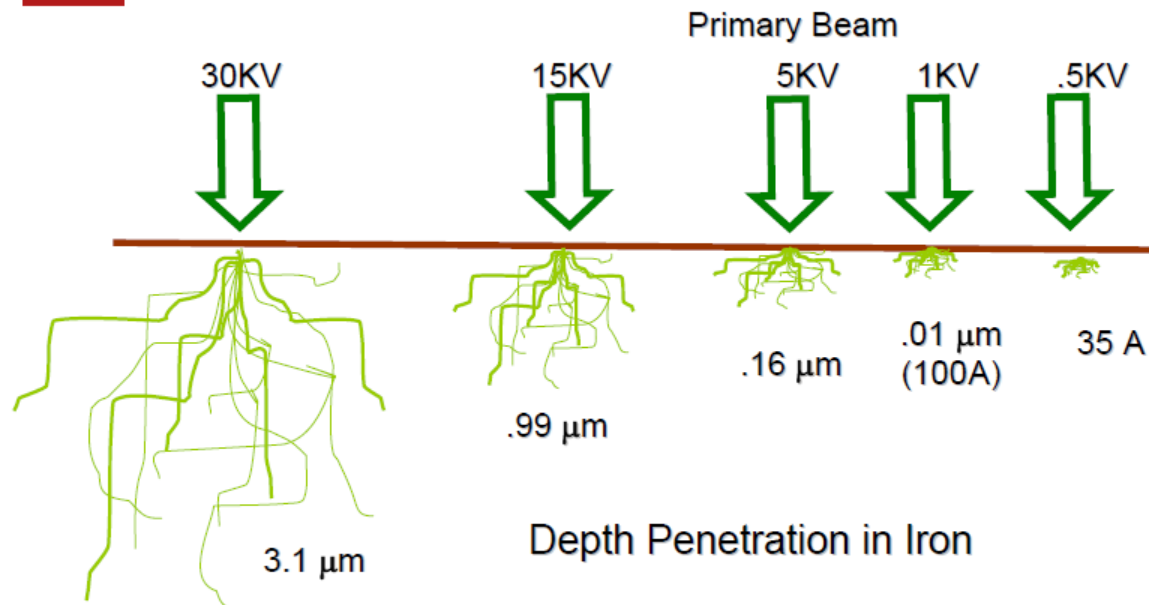
Path of the Electron Beam



Kanaya-Okayama Depth Penetration Formula

$$R = \frac{0.0276 A E^{1.67}}{(Z^{0.89} \rho)} \mu\text{m}$$

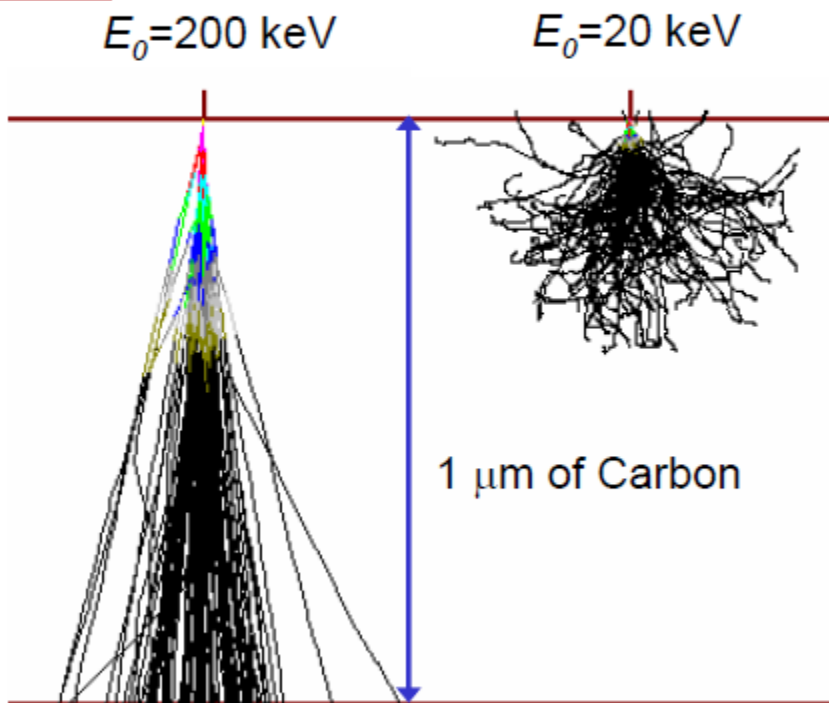
R= Depth Penetration
 A= Atomic Weight (g/mole)
 E= Beam Energy (KV)
 Z= Atomic number
 ρ = density (g/cm)²



(predictions from the KO formula)



Beam Spreading



Electron Range (in μm):

$$R \approx \frac{0.064}{\rho} E_0^{1.5}$$

(density ρ in g/cm^3 , E_0 in keV)

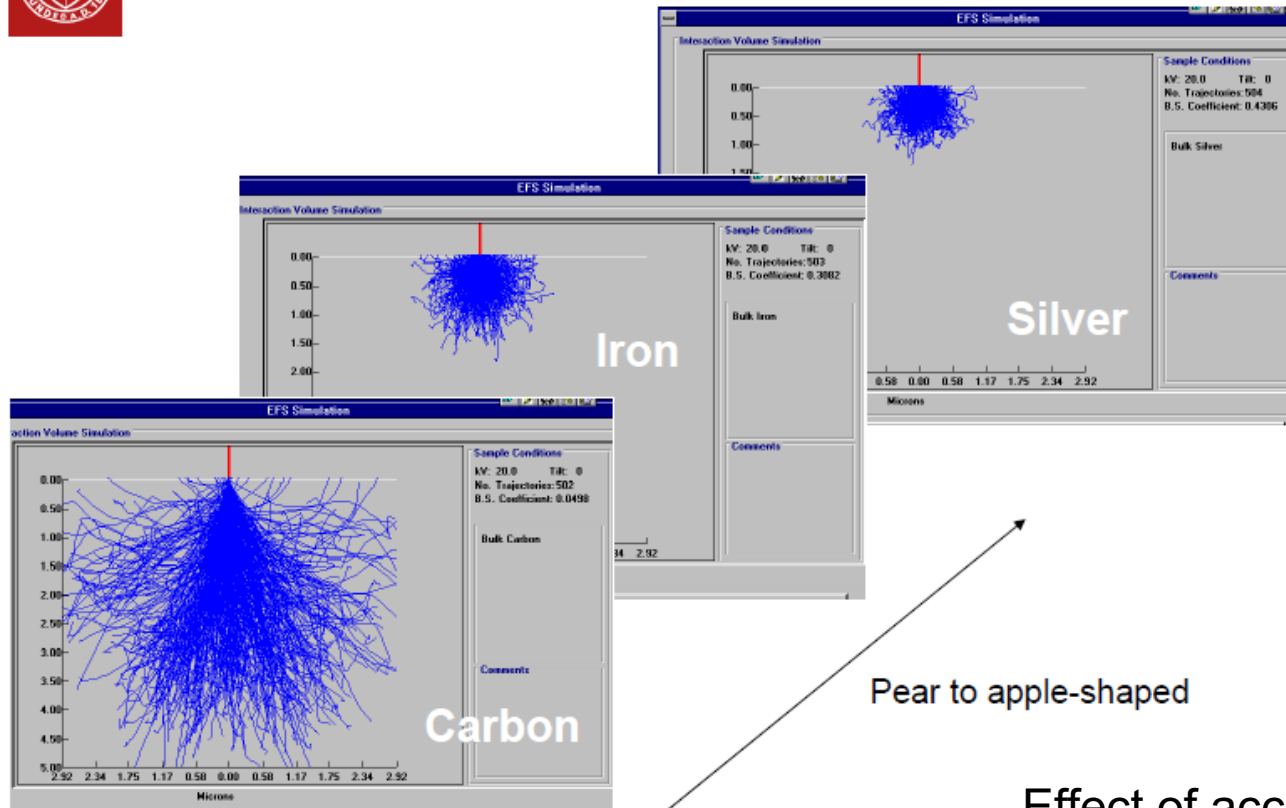
$R \sim 100 \mu\text{m}$ at 200 keV

David Joy's simulation code is available at <http://web.utk.edu/~srcutk/htm/simulati.htm>
A more detailed simulator can be found at <http://www.gel.usherbrooke.ca/casino/What.html>



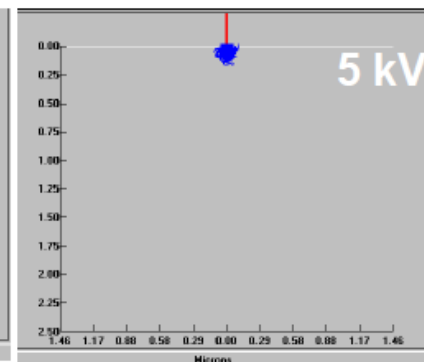
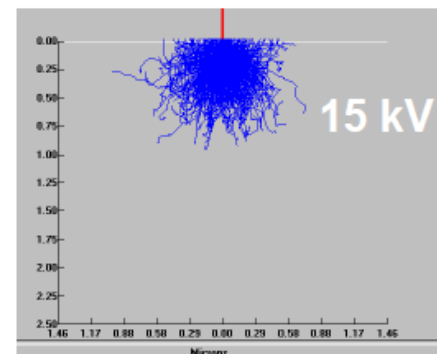
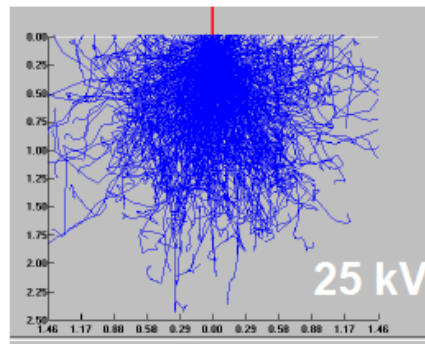
Interaction Volume – Sample Composition

(20 kV incident beam in all 3 cases)



Pear to apple-shaped

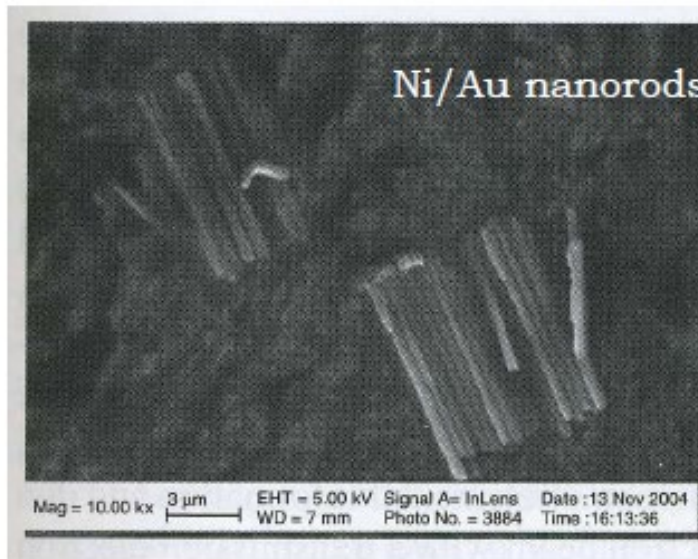
Effect of accelerating voltage



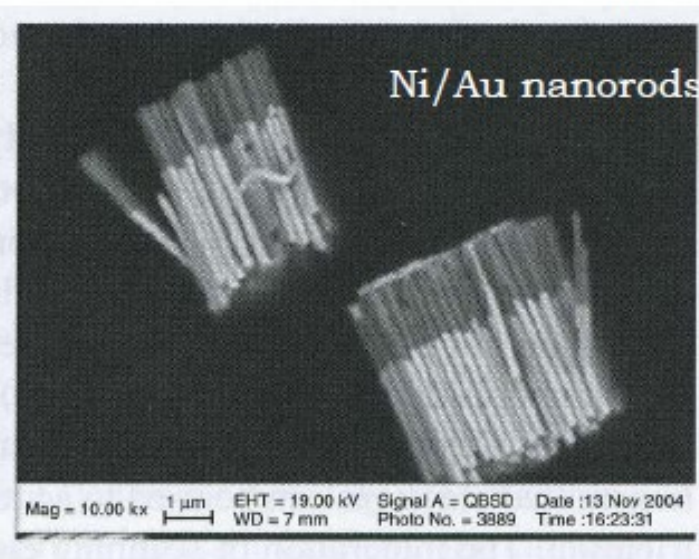
Backscattered electrons

- High energy
- Both Compositional and Topographic information
- Atomic number contrast
- Lateral resolution is worse than secondary electron image

Secondary electron image

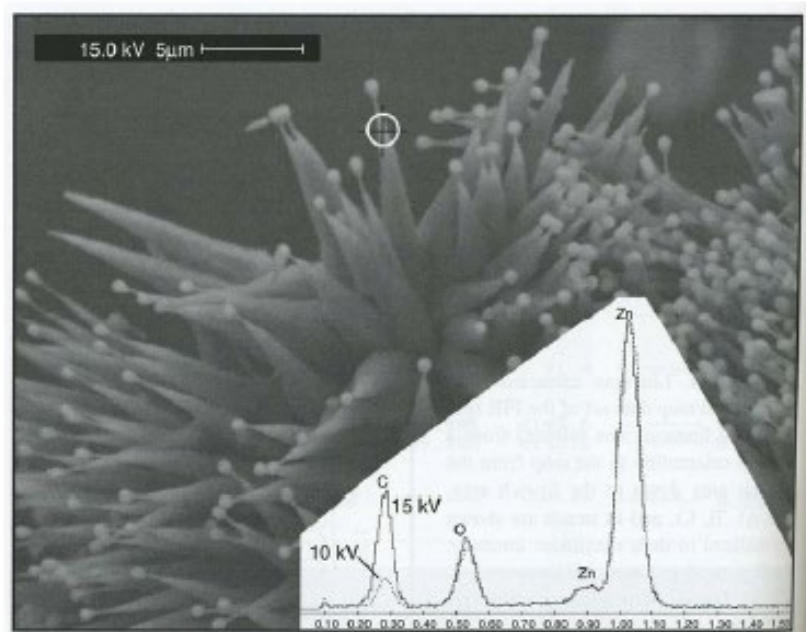
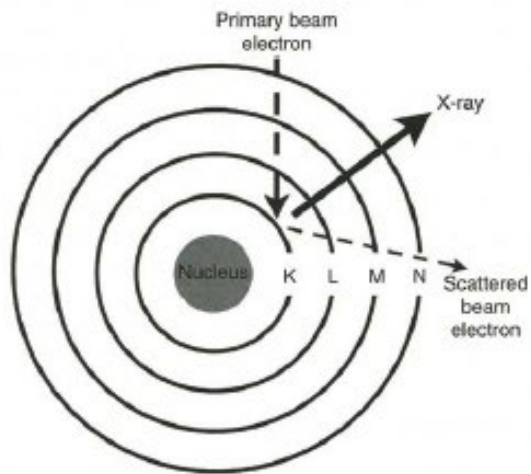


Backscattered electron image



Characteristic X-ray

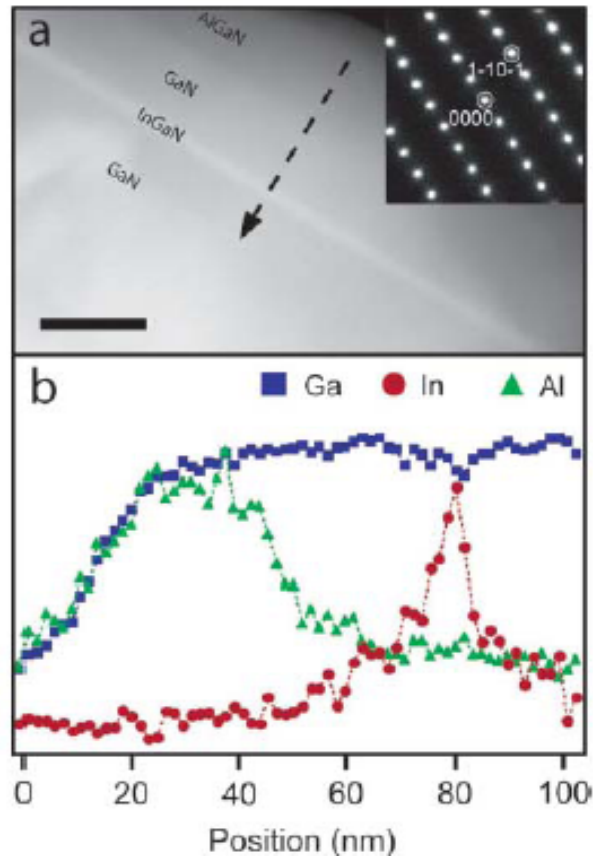
- Chemical information of sample
- Energy Disperse X-ray Spectroscopy (EDS)



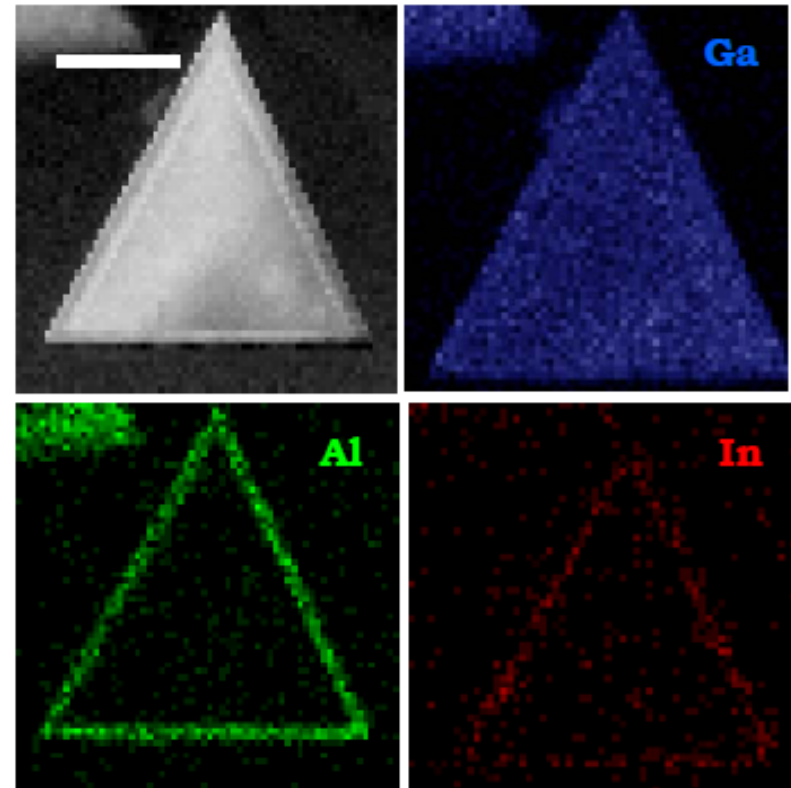
Detection area is limited by the resolution of SEM (accelerating voltage of electron)

Energy Disperse X-ray Spectroscopy (EDS)

Line scan

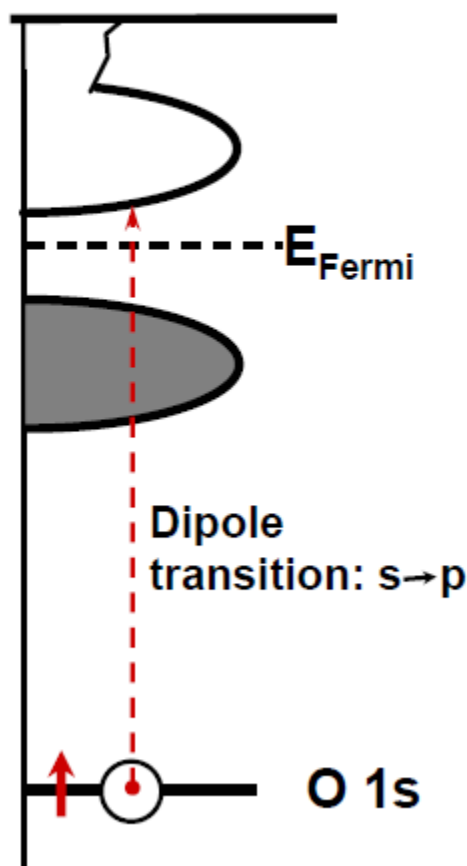


Elemental mapping



Highly resolved spatial distribution of elements in specimen

Core-Level Electron Energy Loss Spectroscopy



EELS measures a local density of states partitioned by

- site - as the probe is localized,
 - element - the core level binding energy is unique
- probes the conduction band
 - provides local electronic information

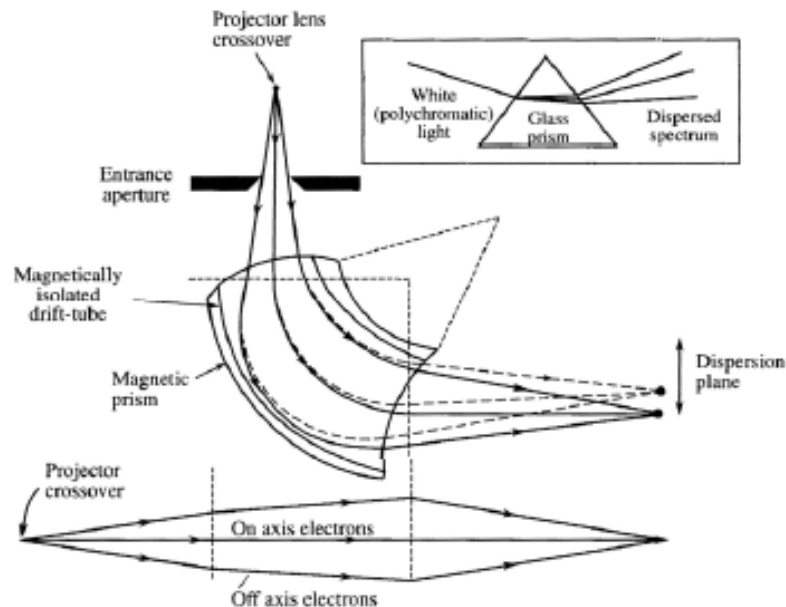
In the first Born approximation, the partial cross section for the inelastic scattering of an electron wave packet (with initial group velocity v), undergoing a momentum transfer \vec{q} and losing energy E ,⁵⁸⁻⁶⁰ is given by

$$\frac{d^2\sigma(E,q)}{dEdq} = \frac{8\pi e^4}{\hbar^2 v^2} \frac{1}{q} \sum_{if} |\hat{\epsilon}_q \cdot \langle f | \vec{r} | i \rangle|^2 \delta(E - E_f + E_i) + \dots$$

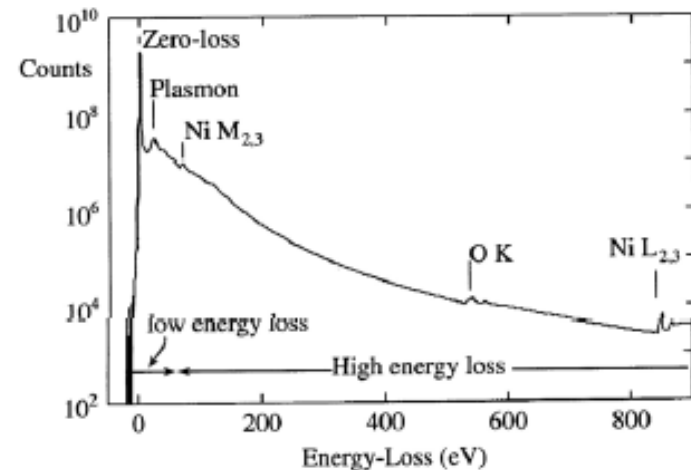
*Some subtleties as to which density of states is measured see Muller, Singh and Silcox, Phys Rev **B57**, 8181 (1998)*

Electron Energy Loss Spectroscopy (EELS)

Magnetic prism spectrometer



- Absorption spectroscopy
- Inelastic scattered electrons



- Complementary to EDS
- High energy resolution
- Atomic composition, chemical bonding, valence and conduction band electronic properties and surface properties
- Ability to fingerprint different forms of the same element

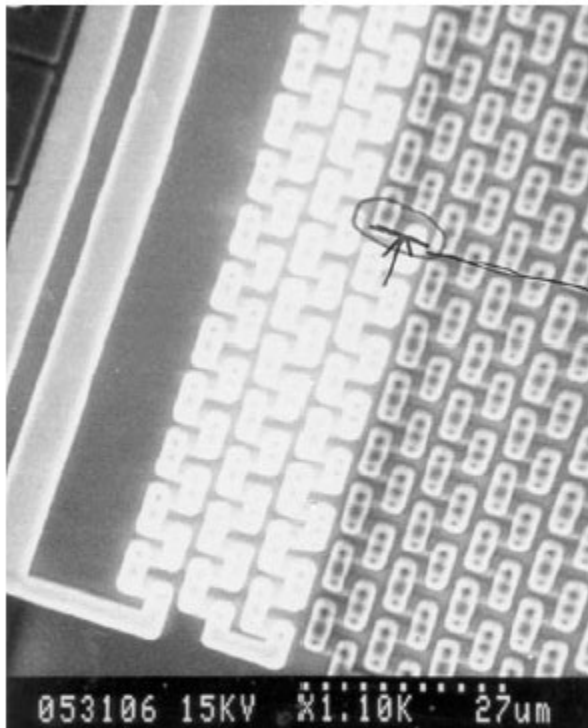
- **EDS**

- *Low collection efficiency (small solid angle)*
- *Good peak/background*
- *Good for high-Z elements*
- *SEM (~500 nm) or TEM (~10 nm)*
- *Stray x-rays in the column can be mistaken for trace elements*

- **EELS**

- *TEM only & thin samples*
- *High collection efficiency (~90%)*
- *Poor peak/background (esp in thick samples)*
- *Best for low-Z elements (large signals)*
- *Bonding information for $Z < 33$*
- *High spatial resolution (0.1 – 1 nm)*

Voltage contrast with SE



The floating end of the via chain is bright because of trapped negative charge causes secondary electrons to be repelled.

The remainder of the chain is neutral, and thus darker.

(<http://www.acceleratedanalysis.com/hepvc.html>)

Sample Coating

Q: Why ?

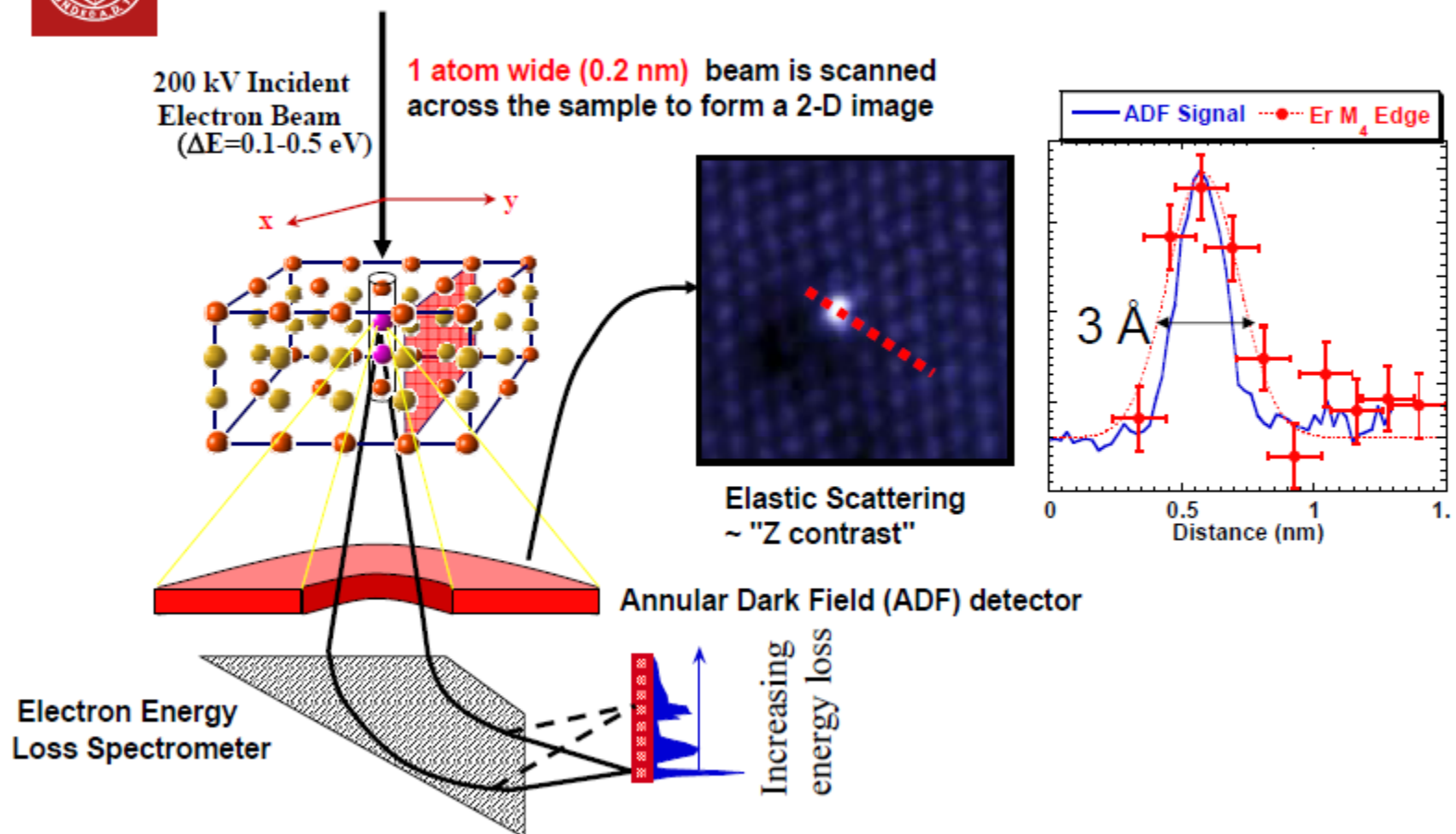
A: Charging:

- **Deflection of SE's**
- **Increased emission of SE's in cracks**
- **Periodic SE bursts**
- **Beam deflection**

Solutions:

- **Sputter coating with C, Cr, or Au-Pd**
- **Carbon tape, carbon paint, In foil**

Scanning Transmission Electron Microscopy



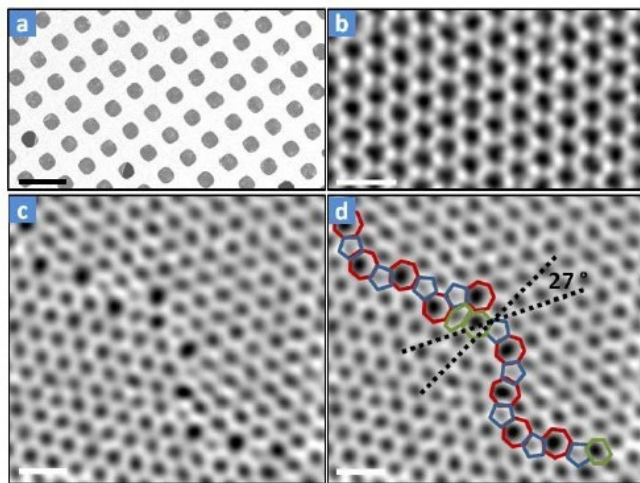
Single atom
Sensitivity:

P. Voyles, D. Muller, J. Grazul, P. Citrin, H. Gossmann, *Nature* **416** 826 (2002)
U. Kaiser, D. Muller, J. Grazul, M. Kawasaki, *Nature Materials*, **1** 102 (2002) 16

Grains and grain boundaries in single-layer graphene atomic patchwork quilts

Pinshane Y. Huang^{1*}, Carlos S. Ruiz-Vargas^{1*}, Arend M. van der Zande^{2*}, William S. Whitney², Mark P. Levendorf³, Joshua W. Kevek⁴, Shivank Garg³, Jonathan S. Alden¹, Caleb J. Hustedt⁵, Ye Zhu¹, Jiwoong Park^{3,6}, Paul L. McEuen^{2,6} & David A. Muller^{1,6}

ADF-STEM



TEM

